RENESAS

ISL91302BIK

Dual/Single Output PMIC with 12-Bit Telemetry ADC for Industrial and Computing Applications

The <u>ISL91302BIK</u> is a highly efficient, dual or single output, synchronous multiphase buck switching regulator that can deliver up to 5A per phase maximum output current. The ISL91302BIK features four integrated power stages and two controllers. The ISL91302BIK can assign its power stages and controllers to two dual-phase outputs (2+2) or one three-phase and one-phase output (3+1) or one-phase output (4+0). This flexibility allows seamless design-in for a wide range of applications in which dual, triple, or quad-phase outputs are needed, such as CPU and GPU core power mobile applications.

ISL91302BIK integrates low ON-resistance MOSFETs at 2MHz switching frequency, allowing very small external inductors and capacitors to be used. With automatic Diode Emulation and Pulse Skipping modes under light-load conditions, this feature improves efficiency and maximizes battery life. The ISL91302BIK delivers a highly robust power solution through a controller based on the Renesas proprietary Rapid Robust Ripple Regulator (R5) technology, offering tight output accuracy and load regulation, ultra-fast transient response, seamless DCM/CCM transitions, and no required external compensation.

In addition to the standard interrupt, chip enable, and watchdog reset functions, the ISL91302BIK also features four MPIOs and two GPIOs that support SPI, I2C communication protocol, external signal telemetry with an internal ADC, Dynamic Voltage Scaling (DVS) with selectable slew rates, and various other pin mode functions.

Features

- Dual output 3+1 or 2+2, or single output 4-phase
- 2.7V to 5.5V supply voltage
- 5A per phase output current capability
- Small solution size
- + High efficiency (94% peak for 3.3V $V_{\text{IN}},\,$ 1.8V $V_{\text{OUT}},\,$ L = 220nH)
- Low I_Q in low power mode
- Proprietary control scheme reduces the output capacitor and supports fast load transients (such as 50A/µs per phase)
- Voltage, current, and temperature telemetry through integrated ADC plus auxiliary inputs
- ±0.7% system accuracy, remote voltage sensing
- I²C and SPI programmable output from 0.3V to 2.0V
- Independent Dynamic Voltage Scaling (DVS) for each output
- Soft-start and fault detection (UV, OV, OC, OT), short-circuit protection
- 4.7mmx 6.3mm 35 ball TFBGA with 0.8mm pin pitch

Applications

- Industrial controls and FPGAs
- · Computing servers and systems
- · Home gateways and applicances

Related Literature

For a full list of related documents, visit our website

<u>ISL91302BIK</u> product page





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1. Overview

1.1 Typical Application Circuits



Figure 3. Typical Application 4-Phase Single Output



Figure 4. Typical Application Circuit: 3-Phase + 1-Phase





Figure 5. Typical Application Circuit: 2-Phase + 2-Phase



1.2 Block Diagram



Figure 6. Block Diagram



1.3 Ordering Information

| Part Number (<u>Notes 1</u> , <u>3</u> , <u>4</u>) | Part Marking | Temp Range (°C) | Tape and Reel (Units) (<u>Note 2</u>) | Package (RoHS Compliant) | Pkg. Dwg. # | | | |
|---|-----------------|---------------------------------------|--|-----------------------------|----------------|--|--|--|
| ISL91302BIKZ-T | 302BK | -40 to +85 | 3k | 4.7mmx6.30mm, 35 ball TFBGA | V35.4.7x6.3 | | | |
| ISL91302BIIK22-EVZ | 2-phase + 2 | 2-phase + 2-phase evlauation board | | | | | | |
| ISL91302BIIK31-EVZ | 3-phase + 1 | 3-phase + 1-phase evlauation board | | | | | | |
| ISL91302BIIK40-EVZ | 4-phase sin | -phase single output evaluation board | | | | | | |

Notes:

- 1. For additional part options contact your local sales office.
- 2. See <u>TB347</u> for details about reel specifications.
- These Pb-free BGA packaged products employ special Pb-free material sets; molding compounds/die attach materials and SnAgCu e6 solder ball terminals, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Pb-free BGA packaged products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
- 4. For Moisture Sensitivity Level (MSL), see the ISL91302BIK device page. For more information about MSL, see TB363.

Table 1. Key Differences Between Family of Parts

| Part Number | Pin Configuration | Pitch | Output Configuration | Maximum Load per Phase |
|-------------|-------------------|-------|-----------------------------|---------------------------|
| ISL91302BIK | 35 Ball 5x7 TFBGA | 0.8mm | Single Output (4+0 Phase) | 5A |
| | 35 Ball 5x7 TFBGA | 0.8mm | Dual Output (3+1 Phase) | 5A |
| | 35 Ball 5x7 TFBGA | 0.8mm | Dual Output (2+2 Phase) | 5A |
| ISL91211AIK | 35 Ball 5x7 TFBGA | 0.8mm | Triple Output (2+1+1 Phase) | 5A |
| ISL91211BIK | 35 Ball 5x7 TFBGA | 0.8mm | Quad Output (1+1+1+1 Phase) | 5A |



1.4 Pin Configuration

JEDEC Standard:

Balls Down, A1 Top Left Corner



35 Ball TFBGA Top View

1.5 Pin Descriptions

| Pin Number | Pin Name | Туре | Description |
|-------------------------------|----------|--------------|---|
| A1 | PVIN_A | Input | Power supply for Power Stage A. |
| A2 | PH_A | Output | Switching node for Power Stage A. |
| A3, B3 | PGND_AB | Input | Ground connection for Power Stage A and B |
| A4 | PH_B | Output | Switching node for Power Stage B. |
| A5 | PVIN_B | Input | Power supply for Power Stage B. |
| B1 | GPIO0 | Input/Output | General purpose I/O pin, see <u>Table 2</u> . |
| B2 | GPIO1 | | |
| B4, C3, C4, D2, D3, D4, E4 | GND | Input | Analog chip ground. Ensure that pin D4 has a low impedance connection to the internal ground layer. |
| B5 | WDOG_RST | Input | Digital input, resets the bucks to default output voltage. |



| Pin Number | Pin Name | Туре | Description |
|------------|-----------|--------------|--|
| C1 | EN | Input | Master chip enable input, NMOS logic threshold. |
| C2 | INT | Output | Interrupt line. |
| C5 | RTN1 | Input | Remote ground voltage sense for Buck #1. |
| D1 | VOUT2 | Input | Remote output voltage sense for Buck #2. |
| D5 | VOUT1 | Input | Remote output voltage sense for Buck #1. |
| E1 | RTN2 | Input | Remote ground voltage sense for Buck #2. |
| E2 | AVIN_FILT | Output | Filtered analog supply voltage, 2.7 to 5.5V. Place a decoupling capacitor close to the IC. |
| E3 | MPIO0 | Input/Output | Multipurpose I/O, see <u>Table 2</u> . |
| E5 | MPIO2 | | |
| F4 | MPIO1 | | |
| F5 | MPIO3 | | |
| F1 | AVIN | Input | Analog supply voltage, 2.7V to 5.5V. |
| F2 | VIO | Input | I/O supply voltage for digital communications. Normally connected to 1.8V supply. |
| F3, G3 | PGND_CD | Input | Ground connection for Power Stage C and D |
| G1 | PVIN_C | Input | Power supply connection for Power Stage C. |
| G2 | PH_C | Output | Switching node for Power Stage C. |
| G4 | PH_D | Output | Switching node for Power Stage D. |
| G5 | PVIN_D | Input | Power supply connection for Power Stage D. |

1.6 I/O Pin Configurations

The ISL91302BIK features two general purpose I/O (GPIO) pins for I²C and other functions, along with four multipurpose I/O (MIO) pins. These pins perform different functions depending on the IO_PINMODE setting. The default factory setting for IO_PINMODE is 0x0. For features requiring IO_PINMODE to be different than the default value, contact Renesas <u>support</u> for factory OTP programming.

| Table 2. | I/O Pin Mode |
|----------|--------------|
|----------|--------------|

| IO_PINMODE | MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 | Description |
|------------|------------|------------|------------|------------|--------|--------|--|
| 0x0 | SCK | SS_B | MOSI | MISO | SCL | SDA | I ² C/SPI both available |
| 0x1 | SCK | SS_B | MOSI | MISO | EN_A | EN_B | SPI mode with hardware enables for Bucks 1-2 |
| 0x3 | SCK | SS_B | MOSI | MISO | DVS1_0 | DVS2_0 | SPI with hardware DVS pins |
| 0x4 | DVS_PIN1 | DVS_PIN0 | PGOOD1 | PGOOD2 | SCL | SDA | I ² C with global DVS mode with PGOOD1 and PGOOD2 |
| 0x5 | BUCK1_DVS0 | BUCK1_DVS1 | BUCK2_DVS0 | BUCK2_DVS1 | SCL | SDA | I ² C with full pin controlled DVS for Buck1 and Buck2 |
| 0x6 | BUCK1_DVS0 | BUCK2_DVS0 | PGOOD1 | PGOOD2 | SCL | SDA | I ² C with DVS and PGOOD for Buck1 and Buck2 |
| 0xD | ADC_IN0 | ADC_IN1 | PGOOD1 | PGOOD2 | SCL | SDA | I ² C with ADC input and PGOOD1 and PGOOD2 |
| 0xE | ADC_IN0 | ADC_IN1 | DVS_PIN1 | DVS_PIN0 | SCL | SDA | I ² C with ADC input and global DVS |

Note: Pinmodes 0x7 through 0xC and 0xF are reserved.



Table 3.Pin Mode Descriptions

| Name | Definition |
|---------------------------|--|
| SCK | SPI clock. |
| SS_B | SPI slave select (must be pulled to VIO when using I ² C). |
| MOSI | SPI master out slave in. |
| MISO | SPI master in slave out. |
| SCL | I ² C clock. |
| SDA | I ² C data. |
| PGOOD1, PGOOD2 | Power-good output pins. PGOOD pins for BUCK1 and BUCK2 |
| EN_A, EN_B | Buck enable input pins. Two buck enable input pins. A single buck enable pin can enable/disable up to two bucks. Enable/disable on a buck can be controlled from one enable pin (EN_A or EN_B) |
| DVS_PIN1, DVS_PIN0 | Global DVS logic pins which references a look-up table to allow complete DVS control. |
| BUCK1_DVS0, BUCK1_DVS1 | DVS input logic pins for Buck1. |
| BUCK2_DVS0, BUCK2_DVS1 | DVS input logic pins for Buck2. |
| ADC_IN0, ADC_IN1 | Input pins for auxiliary ADC. |



2. Specifications

2.1 Absolute Maximum Ratings

| Parameter | Minimum | Maximum | Unit | |
|---|---------|-------------|------|--|
| PVIN and AVIN Pins to PGND | -0.3 | +6 | V | |
| VOUT Pin BUCKx_VOUTFBDIV = 0x0 | -0.3 | +2.0 | V | |
| VOUT Pin BUCKx_VOUTFBDIV = 0x1 | -0.3 | +2.4 | V | |
| VOUT Pin BUCKx_VOUTFBDIV = 0x2 | -0.3 | +3.0 | V | |
| PH to PGND | -0.3 | +0.3 + PVIN | V | |
| VIO EN Pins to GND | -0.3 | +0.3 + AVIN | V | |
| RTN, GND to PGND Pins | -0.3 | +0.3 | V | |
| INT, WDOG_RST, MPIO, GPIO Pins to GND | -0.3 | +0.3 + VIO | V | |
| ESD Ratings (<u>Note 5</u>) | ١ | /alue | Unit | |
| Human Body Model (Tested per JS-001-2017) | | 2 | | |
| Charged Device Model (Tested per JS-002-2014) | | 750 | | |
| Latch-Up (Tested per JESD78E; Class 2, Level A) | | 100 | mA | |

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

Note:

5. ESD ratings apply to external pins only.

2.2 Thermal Information

| Thermal Resistance (Typical) | θ _{JA} (°C/W) | θ _{JC} (°C/W) |
|---|------------------------|------------------------|
| 35 Ball TFBGA Package (<u>Notes 6, 7</u>) | 47 | 3 |

Notes:

6. θ_{JA} is measured in free air with the component mounted on a high-effective thermal conductivity test board with direct attach features. See <u>TB379</u>.

7. For $\theta_{\text{JC}},$ the case temperature location is taken at the package top center.

| Parameter | Minimum | Maximum | Unit |
|------------------------------|---------|------------------|------|
| Maximum Junction Temperature | | +150 | °C |
| Storage Temperature Range | -65 | +150 | °C |
| Pb-Free Reflow Profile | | See <u>TB493</u> | |

2.3 Recommended Operation Conditions

| Parameter | Minimum | Maximum | Unit | |
|---------------------------------------|---------|---------|------|--|
| Junction Temperature | -40 | +125 | °C | |
| Supply Voltage | | | | |
| AVIN to GND | 2.7 | 5.5 | V | |
| PVIN to PGND | 2.7 | 5.5 | V | |
| VIO Voltage (VIO to GND) | 1.7 | AVIN | V | |
| INT, WDOG_RST, MPIO, GPIO Pins to GND | 0 | VIO | V | |



2.4 Analog Specifications

AVIN/PVIN = 3.7V, V_{OUT} = 1V, L = 220nH, Frequency = 2MHz, VIO = 1.8V, T_A = +25°C. Boldface limits apply across the operating junction temperature range, -40°C to +85°C unless otherwise noted.

| Parameter | Symbol | Test Conditions | Min (<u>Note 8</u>) | Тур | Max (<u>Note 8</u>) | Unit |
|---|--------------------|--|--------------------------|------|--------------------------|------|
| Input Supply | | | | | | |
| Supply Voltage | AVIN | | 2.7 | | 5.5 | V |
| Supply Voltage | PVIN | | 2.7 | | 5.5 | V |
| AVIN Supply Current | ا _م | EN = 0V | | 0.1 | 1 | μA |
| AVIN + PVIN Supply Current EN = 0V | | EN = 0V | | <1 | 6 | μA |
| AVIN + PVIN Supply Current | | BUCK1_EN[0] = 0x0 and BUCK2_EN[0] = 0x0 | | 22 | | μA |
| EN = AVIN = PVINx = 3.7V | | 4+0 OTP configuration, not switching BUCK1_EN[0] = 0x1 DCM operation BUCK2_EN[0] = 0x0 | | 75 | | μA |
| | | 4+0 OTP configuration, not switching BUCK1_EN[0] = 0x1 1PH CCM operation BUCK2_EN[0] = 0x0 | | 635 | | μA |
| | | 4+0 OTP configuration, not switching BUCK1_EN[0] = 0x1 4PH CCM operation BUCK2_EN[0] = 0x0 | | 765 | | μA |
| | | 2+2 OTP configuration, not switching BUCK1_EN[0] = 0x0 BUCK2_EN[0] = 0x1 DCM operation | | 85 | | μA |
| | | 2+2 OTP configuration, not switching BUCK1_EN[0] = 0x0 BUCK2_EN[0] = 0x1 1PH CCM operation | | 485 | | μA |
| | | 2+2 OTP configuration, not switching BUCK1_EN[0] = 0x0 BUCK2_EN[0] = 0x1 2PH CCM operation | | 560 | | μA |
| UVLO Rising Threshold | V _{UVLOR} | Rising | 2.52 | 2.60 | 2.67 | V |
| UVLO Falling Threshold | V _{UVLOF} | Falling | 2.28 | 2.34 | 2.39 | V |
| Buck Regulation | | · | | | | |
| Buck Output Voltage Range | V _{OUT} | BUCKx_VOUTFBDIV[1:0] = 0x00 | 0.300 | | 1.2 | V |
| (Each Output) | | BUCKx_VOUTFBDIV[1:0] = 0x01 | 0.375 | | 1.5 | V |
| | | BUCKx_VOUTFBDIV[1:0] = 0x02 | 0.500 | | 2.0 | V |
| Output Voltage Step Size | V _{STEP} | 10-bit control, BUCKx_VOUTFBDIV[1:0] = 0x00 | | 1.2 | | mV |
| | | 10-bit control, BUCKx_VOUTFBDIV[1:0] = 0x01 | | 1.5 | | mV |
| | | 10-bit control, BUCKx_VOUTFBDIV[1:0] = 0x02 | | 2.0 | | mV |
| Output Voltage Accuracy | V _{ACC} | CCM, V _{OUT} > 0.6V | -0.3 | | 0.3 | % |
| (<u>Note 9</u>) | | CCM, V _{OUT} > 0.6V T _A = -10°C to +85°C | -0.7 | | 0.7 | % |
| | | CCM, V _{OUT} < 0.6V | -4 | | 4 | mV |
| | | CCM, V _{OUT} < 0.6V T _A = -10°C to +85°C | -5.5 | | 5.5 | mV |
| Current Matching | IMATCH | I _{OUT} = 5A per phase | | 10 | | % |
| Dynamic Response | | | | | | |
| Dynamic Voltage Scaling (Output Slew Rate) | V _{DVS} | 2.7V < V _{IN} < 5.5V: factory default = 3mV/µs | -15 | | 15 | % |



$AVIN/PVIN = 3.7V, V_{OUT} = 1V, L = 220nH, Frequency = 2MHz, VIO = 1.8V, T_A = +25^{\circ}C.$ Boldface limits apply across the operating junction temperature range, -40°C to +85°C unless otherwise noted. (Continued)

| Parameter | Symbol | Test Conditions | Min (<u>Note 8</u>) | Тур | Max (<u>Note 8</u>) | Unit |
|--|---|--|--------------------------|------|--------------------------|------|
| Boot-Up Time | V _{BT} | Delay from when PVIN, AVIN, and EN are asserted to when the first buck's reference starts ramping. This time includes internal reference startup, OTP load and buck controller calibration time. BUCKx_EN_DELAY = 0x00 | | 1.4 | | ms |
| Frequency | | | | | | |
| CCM Frequency Tolerance | $f_{SW_{TOL}}$ | Factory default = 2MHz | -15 | | 15 | % |
| Power Stage | | | | | | |
| Buck Output Current (Each Phase) | | 2.7V < V _{IN} < 5.5V | | | 5 | A |
| High-Side Switch ON-Resistance | HS r _{DS(ON)} | Conditions: PVIN = 3.7V, Current = 300mA | | 32 | | mΩ |
| Low-Side Switch ON-Resistance | LS r _{DS(ON)} | Conditions: PVIN = 3.7V, Current = 300mA | | 17.5 | | mΩ |
| Protection | | | | | | |
| HSD Current Limit (WOC) | I _{LIMIT} | 2.7V < V _{IN} < 5.5V Phase Count = 2 or more; WOC = 11.35A | -10 | | 10 | % |
| | | 2.7V < V _{IN} < 5.5V Phase Count = 1; WOC = 8.38A | -10 | | 10 | |
| Thermal Shutdown Accuracy | termal Shutdown Accuracy T_{SPS} 2.7V < V_{IN} < 5.5V, factory default = +140°C | | -10 | | 10 | % |
| Thermal Shutdown Hysteresis | ermal Shutdown Hysteresis T_{SPS_HYS} 2.7V < V_{IN} < 5.5V, factory default = +60°C | | -10 | | 10 | % |
| Thermal Warning Alert | ermal Warning Alert T _{ALERT} 2.7V < V _{IN} < 5.5V, factory default = +85°C | | -10 | | 10 | % |
| Thermal Warning Hysteresis | T _{ALERT_HYS} | 2.7V < V _{IN} < 5.5V, factory default = +12°C | -10 | | 10 | % |
| Output OVP Threshold Accuracy | V _{OVP} | Threshold: +250mV | -35 | | 40 | mV |
| Output UVP Threshold Accuracy | V _{UVP} | Threshold: -250mV | -35 | | 35 | mV |
| ADC | | | | | | |
| Output Current Sense Offset | I _{SENSE_OFFSET} | | -75 | | 75 | mA |
| Output Current Sense Accuracy | I _{SENSE_ADC} | I _{LOAD} = 500mA (minus offset) | -10 | | 10 | % |
| | | $3.0V < V_{IN} < 5.0V I_{LOAD} = 500mA$ (minus offset) | -15 | | 15 | % |
| MPIO/GPIO Operating Condition | S | | | | | |
| Allowable Range of Supply for Operation | VIO | | 1.70 | 1.80 | AVIN | V |
| Chip Enable Logic Threshold Lev | /el | | | | | |
| Low-Level Input Voltage | V _{IL} | | | | 0.5 | V |
| High-Level Input Voltage | V _{IH} | | 1.35 | | | V |
| Serial Interfaces | | | | | | |
| I ² C Frequency Capability | f _{I2C} | | | | 3.4 | MHz |
| SPI Frequency Capability | f _{SPI} | | | 26 | | MHz |
| MPIO/GPIO Logic Threshold Lev | vels | | 1 | | L | 1 |
| Low Level Input Voltage | V _{IL} | | | | 0.25 * VIO | V |
| High Level Input Voltage | V _{IH} | | 0.75 * VIO | | | V |
| Hysteresis on Input | V _{HYS} | | 0.1 * VIO | | | V |



 $AVIN/PVIN = 3.7V, V_{OUT} = 1V, L = 220nH$, Frequency = 2MHz, $VIO = 1.8V, T_A = +25^{\circ}C$. Boldface limits apply across the operating junction temperature range, -40°C to +85°C unless otherwise noted. (Continued)

| Parameter | Symbol | Test Conditions | Min (<u>Note 8</u>) | Тур | Max (<u>Note 8</u>) | Unit |
|-------------------|-----------------|-----------------|--------------------------|-----|--------------------------|------|
| Low Level Output | V _{OL} | 1mA | | | 0.4 | V |
| High Level Output | V _{OH} | 1mA | VIO - 0.4 | | | V |

Note:

8. Compliance to datasheet limits is assured by one or more methods: production test, characterization, and/or design.

9. V_{OUT} feedback divider ratio equals 1 (BUCKx_VOUTFBDIV[1:0] = 0x00).

10. As per <u>"Thermal Information" on page 10</u>, operating beyond thermal limits can cause permanent damage.



3. Output Configurations

Table 4. Output Configurations

| Output Configuration | Power Stage Assignment | | | | Diagram | | |
|---|--|----------|------------|-----------|----------------------|-------------------|----------------|
| 4-Phase | 4-Phase: Buck #1 (VOUT1) | | | 4+(| 0 Configuration | | |
| Connect VOUT2 and RTN2 to PGND Plane | • Ph1: PH_A • Ph2: PH_B • Ph3: PH_D • Ph4: PH_C | | (pvin_a) | | (PGND_) (A_B | (-PH_B) | (PVIN_B) |
| | | | (GPI00) | (GPI01) | (PGND_) (A_B | (GND) | (WDOG_) RST |
| | | | () | (INT) | | (GND) | (RTN1 |
| | | | (vout2) | (GND) | | (GND) | (vout1 + |
| | | <u> </u> | (RTN2) | (AVIN_FI) | (MPIO0) | (GND) | (MPIO2) |
| | | | (AVIN) | (vio) | (PGND_) (C_D | (MPIO1) | (MPIO3) |
| | | | (PVIN_C) | (PH_C) | (PGND_) (C_D) | / - \ (PH_D) | (PVIN_D) |
| | | | PH1 | PH4 S | | PH3 | |
| | | | | | | | |

| Output Configuration | Power Stage Assignment | Diagram | |
|-------------------------|--|---|--|
| 3-Phase + 1-Phase | 3+1 Configuration: • 3-phase: Buck #1 | 3+1 Configuration | |
| | (VOUT1) Ph1: PH_A Ph2: PH_B Ph3: PH_D • 1-phase: Buck #2 | PH1 PH3 PH2 RTN1 | |
| | (V _{OUT2}) Ph1: PH_C | $(PVIN_A) (PH_A) (PH_B) (PVIN_B)$ | |
| | | $\begin{pmatrix} GPIO0 \end{pmatrix} \begin{pmatrix} GPIO1 \end{pmatrix} \begin{pmatrix} PGND_{-} \\ A_{-}B \end{pmatrix} \begin{pmatrix} GND \end{pmatrix} \begin{pmatrix} WDOG_{-} \\ RST \end{pmatrix}$ | |
| | | (EN) (INT) (GND) (GND) (RTN1+ | |
| | | (VOUT2) (GND) (GND) (VOUT1) | |
| | | (RTN2) (AVIN_FI) LT (MPIO0) (GND) (MPIO2) | |
| | | $\begin{pmatrix} (AVIN) \\ (VIO) \\ (VIO) \\ (VIO) \\ (C_D) \\ (MPIO1) \\ (MPIO3) \\ ($ | |
| | | $(PVIN_C)$ (PH_C) (PH_C) (PH_D) $(PVIN_D)$ $(PVIN_D)$ $(PVIN_D)$ | |
| | | VOUT2 | |

Table 4. Output Configurations (Continued)

| Output Configuration | Power Stage Assignment | Diagram | |
|-------------------------|--|--|-----------------|
| 2-Phase + 2-Phase | 2+2 Configuration • 2-phase: Buck #1 | 2+2 Configuration | |
| | (VOUT1) Ph1: PH_A Ph2: PH_B • 2-phase: Buck #2 (V _{OUT2}) Ph1: PH_C | PH1 PH2 PH2 | ⁻ N1 |
| | Ph2: PH_D | $(PVIN_A] (PH_A) (PGND_) (PH_B) (PVIN_A] (PH_B)$ | /п_в) |
| | | | |
| | | (EN) (INT) (GND) (GND) (R | TN1 |
| | | (VOUT2+) (GND) (GND) (GND) (VV | ЭUT1) |
| | | (AVIN_FI) (MPIO0) (GND) (M | PIO2] |
| | | $\begin{pmatrix} AVIN \\ - & - & - \end{pmatrix} \begin{pmatrix} VIO \\ - & - & - \end{pmatrix} \begin{pmatrix} PGND \\ C_D \\ - & - \end{pmatrix} \begin{pmatrix} MPIO1 \\ - & - & - \end{pmatrix} \begin{pmatrix} MPIO1 \\ - & - & - \end{pmatrix} \begin{pmatrix} MPIO1 \\ - & - & - & - \end{pmatrix}$ | PIO3] |
| | | (PVIN_C) (PVIN_C) (PH_C) (PH_C) (PH_C) (PH_D) (PLC) (PH_D) (PLC) (PLC) (PH_C) (PLC) (PLC) | |
| | | PH1 PH2 | |
| | | | |

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4. Typical Operating Performance

Unless otherwise noted, operating conditions are: V_{IN} = 3.8V, V_{OUT} = 1.1V, VIO and Enable = 1.8V, T_A = +25°C, f_{SW} = 2MHz, 2-phase operation, L = 220nH, C_{OUT} = 5x22µF.





Unless otherwise noted, operating conditions are: V_{IN} = 3.8V, V_{OUT} = 1.1V, VIO and Enable = 1.8V, T_A = +25°C, f_{SW} = 2MHz, 2-phase operation, L = 220nH, C_{OUT} = 5x22µF. (Continued)



Figure 13. 2-Phase V_{OUT} vs V_{IN} (10mA to 10A)



Figure 14. Single Phase V_{OUT} vs V_{IN} (10mA to 5A)



Figure 15. PVIN Quiescent Current (PFM Mode)

110 Vout = 0.75V Vout = 0.9V Vout = 1.1V 105 Quiescent Current (µA) 100 95 90 85 80 3.3 3.8 4.3 4.8 5.3 5.8 2.8 Input Voltage (V)

Figure 16. PVIN Quiescent Current (PWM Mode)



Figure 17. PVIN Quiescent Current (No Switching)





Unless otherwise noted, operating conditions are: V_{IN} = 3.8V, V_{OUT} = 1.1V, VIO and Enable = 1.8V, T_A = +25°C, f_{SW} = 2MHz, 2-phase operation, L = 220nH, C_{OUT} = 5x22µF. (Continued)



Figure 22. Dual-Phase Transient



Figure 23. Single-Phase Transient



5. Applications Information

5.1 Inductor Selection

The ISL91302BIK is a high efficiency, high performance, dual output multiphase/single-phase synchronous buck converter that can deliver up to 5A of peak current per phase at 0.3V to 2.0V regulated voltage. The ISL91302BIK operates as one quad-phase output (4+0), one three-phase and one single-phase output (3+1), or two dual-phase outputs (2+2) at a switching frequency fixed at 2MHz. Switching MOSFETs are fully integrated and no additional external MOSFETs or diodes are needed. Each phase requires an equal external inductor, that can deliver up to the maximum load current divided by the number of phases used.

| Manufacturer | Part Number | L x W x H (mm) | Value (nH) | DCR mΩ (Typ) | I _{SAT} (Тур) |
|--------------|---------------|----------------|------------|--------------|------------------------|
| Cyntec | HMLB25201T | 2.5x2.0x1.0 | 220 | 9.4 | 7.0 |
| Taiyo Yuden | MAKK2520HR22M | 2.5x2.0x1.0 | 220 | 16 | 8.5 |
| Cyntec | HTTN2016T | 2.0x1.6x1.0 | 220 | 13 | 7.2 |
| Murata | DFE2016E | 2.0x1.6x1.0 | 240 | 16 | 7.0 |
| Murata | DFE252012F | 2.5x2.0x1.2 | 470 | 23 | 6.7 |

Table 5. Recommended Output Inductors

5.2 Output Capacitor Selection

Output capacitors are needed to provide filtering of square voltage at the phase node into a regulated output voltage. The amount of output capacitance required is based on the parameters of the maximum load step, the slew rate of the load step, and the maximum allowable voltage regulation tolerance during the transient. The amount of ripple voltage at the output capacitor is also a design constraint; the total peak-to-peak ripple voltages produced from the output capacitor is equal to its ESR multiplied by the worst case inductor ripple current.

Make sure to select X7R or X5R type capacitors and consider for DC bias effects. A wide range of output capacitor values can be used.

| Table 6. | Recommended Output Capacitors |
|----------|--------------------------------------|
|----------|--------------------------------------|

| Manufacturer | Part Number | Case Size | Value (µF) | Voltage Rating (V) |
|--------------|---------------------|-----------|------------|--------------------|
| ТДК | C1608X5R1A226M080AC | 0603 | 22 | 10 |
| TDK | C0510X6S0G105M030AC | 0204 | 1 | 4 |
| Murata | LLD154R60G435ME01 | 0402 | 4.3 | 4 |
| Murata | LLL1U4R60G435ME22 | 0204 | 4.3 | 4 |

5.3 Input Capacitor Selection

Ceramic input capacitors source the AC component of the input current flowing into the high-side MOSFETs. Place them as close to the IC as possible. A 10 μ F local decoupling capacitor is recommended for each phase PVIN. If long wires are used to bring power to the IC, use additional Bulk capacitors between C_{IN} and the battery/power supply to dampen ringing and overshoot at start-up.

Internal analog reference circuits also require additional filtering at the AVIN_FLT pin.

| Manufacturer | Part Number | Case Size | Value (µF) | Volt (V) | Input |
|--------------|----------------------|-----------|------------|----------|-------|
| TDK Corp | CGB2A1X5R1A105M033BC | 0402 | 1 | 10 | AVIN |
| Kemet | C0402C104K8RACTU | 0402 | 0.1 | 10 | AVIN |
| Samsung | CL05A10MP5NUNC | 0402 | 10 | 10 | PVIN |
| Murata | GRM188R61A106MAAL | 0603 | 10 | 10 | PVIN |



5.4 ADC Telemetry

The ISL91302BIK has an internal SAR ADC that monitors and reports the die temperature, individual phase currents, total buck output current, output voltage, and input voltage. Two additional channels provide internal or external monitoring. Using these channels requires OTP programming from the factory. The ADC is OTP programmed to be turned off during Discontinuous Conduction mode to save current and improve light-load efficiency.

Reading the ADC output is accomplished by reading the respective MSB (8-bit) and LSB (8-bit). <u>Table 8</u> shows which registers hold the ADC data.

| Monitor | Register Name | Register Address MSB | Register Address LSB |
|---------------------|---------------|----------------------|----------------------|
| Temperature | SAMPLE0 | 0x16 | 0x17 |
| Buck1 Ph1 Current | SAMPLE1PH1 | 0x18 | 0x19 |
| Buck1 Ph2 Current | SAMPLE1PH2 | 0x1A | 0x1B |
| Buck1 Ph3 Current | SAMPLE1PH3 | 0x1C | 0x1D |
| Buck1 Ph4 Current | SAMPLE1PH4 | 0x1E | 0x1F |
| Buck1 Total Current | SAMPLE1T | 0x20 | 0x21 |
| PVIN for Buck1 | SAMPLE2 | 0x22 | 0x23 |
| VOUT1 | SAMPLE3 | 0x24 | 0x25 |
| Buck2 Ph1 Current | SAMPLE4PH1 | 0x26 | 0x27 |
| Buck2 Ph2 Current | SAMPLE4PH2 | 0x28 | 0x29 |
| Buck2 Total Current | SAMPLE4T | 0x2A | 0x2B |
| PVIN for Buck2 | SAMPLE5 | 0x2C | 0x2D |
| VOUT2 | SAMPLE6 | 0x2E | 0x2F |
| AUX INPUT0 | AUX0 | 0x30 | 0x31 |
| AUX INPUT1 | AUX1 | 0x32 | 0x33 |

Table 8. ADC Register Addresses

The ADC 16-bit output is a signed format in which the LSB is 0.25 when referring to temperature, voltage, or individual phase current. The total buck current measurement has an LSB of 1. Each channel is filtered through an internally programmable IIR filter. AUX input 0 and AUX input 1 allow the user to read the external values with the ISL91302BIK ADC.

Table 9. ADC Result Registers

| Units | Phase Current (mA) | Total Buck Current (mA) | Temperature (°C) | Voltage (mV) |
|--------|--------------------|-------------------------|------------------|--------------|
| 0x0000 | 0 | 0 | 0 | 0 |
| 0x0001 | 0.25 | 1 | 0.25 | 0.25 |
| 0x0002 | 0.5 | 2 | 0.5 | 0.5 |
| 0x0003 | 0.75 | 3 | 0.75 | 0.75 |
| 0x0004 | 1 | 4 | 1 | 1 |
| | | | | |
| 0x0010 | 4 | 16 | 4 | 4 |
| | | | | |
| 0x0100 | 64 | 256 | 64 | 64 |
| | | | | |
| 0x7FFF | 8191.75 | 32767 | 8191.75 | 8191.75 |
| 0x8000 | -8192 | -32768 | -8192 | -8192 |



| Units | Phase Current (mA) | Total Buck Current (mA) | Temperature (°C) | Voltage (mV) |
|--------|--------------------|-------------------------|------------------|--------------|
| 0x8001 | -8191.75 | -32767 | -8191.75 | -8191.75 |
| | | | | |
| 0xFFFF | -0.25 | -1 | -0.25 | -0.25 |

Table 9. ADC Result Registers (Continued)

5.5 Dynamic Voltage Scaling (DVS)

The ISL91302BIK has several options to achieve DVS. Each buck controller has four independently programmable voltage settings to set the output voltage. The settings are DVS0, DVS1, DVS2, and DVS3. Changing the selected DVS number selects the corresponding output voltage. The two methods to select the DVS are:

Method 1) - Use internal registers to select DVS by writing to the BUCKx_DVSSELECT[1:0] bits in the BUCKx_DVSSEL register for each respective buck using SPI or I^2C .

To use this method, the BUCKx_DVSCTRL[0] bit has to be set to 0x0 for the corresponding buck. The BUCKxDVSSELECT[1:0] setting allows the user to switch between the four different DVS settings, each of which corresponds to a set of DVS registers holding the DVS information.

For example, DVS0 correponds to BUCKx_DVS0VOUT92[7:0] and BUCKx_DVS0VOUT10[1:0]. The two register values combined represent the complete 10-bit DAC code for DVS0.

Table 10. DVS Method Selection

| BUCKx_DVSCTRL[0] | | | |
|------------------|---|--|--|
| 0x0 | Use BUCKx_DVSSELECT[1:0] to select active DVS configuration | | |
| 0x1 | Use DVS pin(s) to control DVS selection | | |

Table 11. DVS Pointers

| BUCKx_DVSSELECT[1:0] | Active DVS for BUCKx |
|----------------------|----------------------|
| 0x0 | DVS0 |
| 0x1 | DVS1 |
| 0x2 | DVS2 |
| 0x3 | DVS3 |

Each output voltage is set writing a 10-bit word to DVS Configuration 1 (BUCKx_DVS0CFG1 register) and DVS Configuration 0 (BUCKx_DVS0CFG0 register) in each buck. Configuration 1 holds the eight most significant bits and Configuration 0 holds the last two bits of the 10-bit word. The output voltage does not change until the LSB register has been written. Table 12 shows the relationship between the DVS word and V_{OUT}.

Table 12. 10-Bit DVS Code to Voltage Translation

| FBDIV | 1.0 | 0.8 | 0.6 |
|-----------|----------------------|----------------------|----------------------|
| DAC [9:0] | V _{OUT} (V) | V _{OUT} (V) | V _{OUT} (V) |
| 0x000 | 0.0000 | 0.0000 | 0.0000 |
| 0x001 | 0.0012 | 0.0015 | 0.0020 |
| | | | |
| 0x200 | 0.6144 | 0.768 | 1.024 |
| 0x201 | 0.6156 | 0.7695 | 1.026 |
| | | | |
| 0x3E8 | 1.2 | 1.5 | 2.0 |



Method 2) - Using GPIO/MPIO pins to achieve DVS, there are five variations depending on the IO_PINMODE register setting. See <u>Table 2</u>.

NOTE: To use DVS by GPIO/MPIO pins requires IO_PINMODE to be OTP programmed before a start-up boot sequence is initiated. On-the-fly programming is not recommended for the following configurations.

(i) IO_PINMODE = 0x3: SPI with two Independent Buck DVS pins

| MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 |
|-------|-------|-------|-------|--------|--------|
| SCK | SS_B | MOSI | MISO | DVS1_0 | DVS2_0 |

BUCKx_DVSCTRL[0] should be OTP programmed high before the start-up sequence. The active DVS follows the DVSx_0 pin logic for the respective buck. See <u>Table 13</u> for more information.

Table 13. Single DVS Pin Logic

| Function | | | |
|----------|----------------------|--|--|
| DVS1_0 | Active DVS for BUCK1 | | |
| 0 | DVS0 | | |
| 1 | DVS1 | | |
| DVS2_0 | Active DVS for BUCK2 | | |
| 0 | DVS0 | | |
| 1 | DVS1 | | |

(ii) IO_PINMODE = 0x4: I²C with Global DVS and PGOOD pins

| MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 |
|----------|----------|--------|--------|-------|-------|
| DVS_PIN1 | DVS_PIN0 | PGOOD1 | PGOOD2 | SCL | SDA |

BUCKx_DVSPIN_CTRL[1:0] bits in BUCKx_DVSCFG register in combination with the DVS_PIN1 and DVS_PIN2 sets the active DVS for the respective BUCK. See <u>Table 14</u> for more information. BUCKx_DVSCTRL[0] should be OTP programmed high before the start-up sequence.

Table 14. Global DVS Pin Logic

| BUCKx_DVSPIN_CTRL[1:0] | DVS_PIN1 | DVS_PIN0 | Active DVS |
|------------------------|----------|----------|------------|
| 0x0 | Х | X | DVS0 |
| 0x1 | Х | 0 | DVS0 |
| | Х | 1 | DVS1 |
| 0x2 | 0 | X | DVS0 |
| | 1 | X | DVS2 |
| 0x3 | 0 | 0 | DVS0 |
| | 0 | 1 | DVS1 |
| | 1 | 0 | DVS2 |
| | 1 | 1 | DVS3 |

Note: The 'X' indicates that either a 0 or 1 is acceptable.



(iii) **IO_PINMODE = 0x5**: I²C with 2 DVS pins for Buck1 and 2 DVS pins for Buck2

| MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 |
|--------|--------|--------|--------|-------|-------|
| DVS1_0 | DVS1_1 | DVS2_0 | DVS2_1 | SCL | SDA |

The active DVS is selected based off the combined $DVSx_1$ and $DVSx_2$ input pin logic. See <u>Table 15</u> for more information. BUCKx_DVSCTRL[0] should be OTP programmed high before the start-up sequence.

Table 15. Active DVS for 2 DVS Pins Configuration

| DVSx_1 | DVSx_0 | Active DVS for BUCKx |
|--------|--------|----------------------|
| 0 | 0 | DVS0 |
| 0 | 1 | DVS1 |
| 1 | 0 | DVS2 |
| 1 | 1 | DVS3 |

(iv) IO_PINMODE = 0x6: I²C with 2 DVS pins and 2 PGOOD pins

| MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 | |
|--------|--------|--------|--------|-------|-------|--|
| DVS1_0 | DVS2_0 | PGOOD1 | PGOOD2 | SCL | SDA | |

BUCKx_DVSCTRL[0] should be OTP programmed high before the start-up sequence. DVS1_0 and DVS2_0 follows the same active DVS table as in IO_PINMODE = 0x3. See <u>Table 13</u> for more information.

(v) IO_PINMODE = 0xE: I2C with 2 DVS pins and 2 AUX ADC pins

| MPIO0 | MPIO1 | MPIO2 | MPIO3 | GPIO0 | GPIO1 | |
|---------|---------|----------|----------|-------|-------|--|
| ADC_IN0 | ADC_IN1 | DVS_PIN1 | DVS_PIN2 | SCL | SDA | |

DVS_PIN0 and DVS_PIN1 behave the same as in IO_PINMODE = 0x4. See <u>Table 14</u> for more information. BUCKx_DVSCTRL[0] should be OTP programmed high before the start-up sequence.

5.6 Configuring DVS Speed

5.6.1 Power-Up and Shutdown Slew Rate Setting

The BUCKx_RSPPUP[2:0] bits in the BUCKx_RSPCFG0 register set the slew rates (DVS speed) in BUCKx only during V_{OUTx} power-up. Similarly, the BUCKx_RSPPDN[2:0] in the BUCKx_RSPCFG0 register sets the slew rates in BUCKx during normal V_{OUTx} shutdown. The achievable slew rates varies with different FBDIV settings (Factory OTP programmed). For more details, see Register <u>BUCK1_RSPCFG0</u>.

5.6.2 DVS Transition Slew Rate Setting

BUCKx_RSPUP[2:0] and BUCKx_RSPDN[2:0] in the BUCKx_RSPCFG1 register sets the slew rates (DVS speed) in BUCKx during normal DVS transiton. The achievable slew rates varies with different FBDIV settings (factory OTP programmed). For more details, see Register <u>BUCK1_RSPCFG1</u>.

5.7 Output Voltage Setting

Each output voltage is set by writing a 10-bit word to DVS Configuration 1 (BUCKx_DVS0CFG1 register) and DVS Configuration 0 (BUCKx_DVS0CFG0 register) in each buck. Configuration 1 holds the MSB and Configuration 0 holds the last two bits of the 10-bit word. The output voltage does not change until the LSB register has been written. <u>BUCK1_DVS0CFG1</u> shows the relationship between the DVS word and V_{OUT}.



5.8 Power Sequencing

When the master chip Enable (EN) pin is brought above an NMOS threshold, the ISL91302BIK powers up its key biasing circuits, loads the OTP configuration registers, and does one of two things based on the preprogrammed OTP setting:

1. Manual buck start-up:

Program the internal IO_BUCKx_EN bits to 1 from I²C/SPI to enable the respective buck. When IO_PINMODE = 0x1, the EN_A and EN_B pins can also be used to enable the respective bucks. If using IO_PINMODE = 0x1, the internal IO_BUCKx_EN bits should be set high in OTP. The slew rate of each buck during its soft-start is specified by the BUCKx_RSPPUP[2:0] bits.

Note: The programmable (1ms to 63ms) delay using BUCKx_EN_DLY[5:0] is not used for Manual Buck start-up.

2. Auto Buck start-up from master chip enable pin:

Run a predetermined start-up sequence for the buck outputs as soon as BOOT is complete. The slew rate of each buck during its soft-start is specified in BUCKx_RSPPUP[2:0].

Note: The delay, BUCKx_EN_DLY[5:0] shown in Figure 24 as EN_dlyx, is programmable from 0 to 63ms in 1ms steps.

<u>Figure 24</u> provides an example of power-up configurability. The master chip enable pin (EN) transitions from 0 to 1 and OTP is loaded over 1.4ms. After the initial 1.4ms boot interval, the buck output start-up sequence begins. In the <u>Figure 24</u> example, BUCK1_EN_DLY is set for 0ms and BUCK2_EN_DLY is set for 1ms.



Figure 24. Master Chip Enable Power-Up Example

The buck outputs can also be programmed to execute a controlled shutdown in two ways:

1. Manual buck power-down:

Program the internal IO_BUCKx_EN bit to 0 through I^2C/SPI or lower the Buck Enable pin (EN_A or EN_B when IO_PINMODE = 0x1). The manual method can be used to power down a specific buck (with a controlled slew rate) while keeping the rest of the chip alive.

Note: The programmable (0ms to 63ms) delay from BUCKx_SHUTDN_DLY[5:0] is not used for manual buck power-down.

2. Auto Buck power-down from master chip enable pin:

When the master chip Enable pin (EN) is brought below the falling threshold of the comparator, the Bucks are ramped down at a controlled rate using preprogrammed delays. This is then followed by the power-down of the bias circuits forcing the chip into shutdown. The slew rate of each buck during its power-down (down to \sim 250mV) is specified in BUCKx_RSPPDN[2:0].

Note: The delay, BUCKx_SHUTDN_DLY[5:0] shown in <u>Figure 25</u> as Dis_dlyx, is programmable from 0 to 63ms in 1ms steps.

<u>Figure 25</u> provides an example of power-down configurability. The master chip enable pin (EN) transitions from logic 1 to 0. In the <u>Figure 25</u> example, BUCK1_SHUTDN_DLY is set for 1ms and BUCK2_SHUTDN_DLY is set for 2ms.





Figure 25. Auto Chip Power-Down Example

The actual slew rate that each buck ramps down to is specified by the register BUCKx_RSPSHUTDN. This slew rate is controlled until the output voltage is ~250mV, at which point the ISL91302BIK engages a weak resistive pull-down (if enabled by factory OTP) that can keep $V_{OUT} = 0V$ when the buck is not enabled. Figure 26 shows an example of the weak pull-down behavior.

• **Option 1:** If the disable event for a buck output is the master chip enable pin (EN) falling below its logic low threshold, then when the output falls below 250mV, the output voltage decay is dictated by the system load passively discharging the buck output capacitance. PULL_DOWN_DISCHARGE IO_MPIO_DATA[4] bit per the IO_MPIO_DATA register is **not** used in this method.

• **Option 2:** If the disable event for a buck output is the master chip enable pin (EN) remaining high and the enable register bit (IO_BUCKx_EN) transitioning from a logic 1 to a logic 0, then PULL_DOWN_DISCHARGE IO_MPIO_DATA[4] bit per the IO_MPIO_DATA register is used enabling an internal weak pull down.

Note: The weak pull-down can be disabled (using factory OTP).



Figure 26. Buck Disable Waveform

5.9 Watchdog Time (WDOG_RST Pin)

The ISL91302BIK implements a watchdog function which allows the output voltages to return to a safe default when communication to the processor host is lost. This is determined by monitoring the state of the WDOG_RST pin. If the pin goes into the failure state for a duration greater than the programmed debounce time, the default voltages from OTP are restored.

Both bucks respond to the WDOG_RST pin. The polarity of the WDOG_RST pin is active low.

Table 16. WDOG_RST Function

| Action | | | | |
|---------------------|--|--|--|--|
| At Boot Up | DVS registers are loaded with values stored in OTP. | | | |
| After Debounce Time | Restore selected output voltages to their original values stored in OTP (DVS0), and slew the buck outputs to that voltage. | | | |

Total recovery time for the buck is the sum of the t_{SLEW} and $t_{DEBOUNCE}$. The target voltage WDOG_RST pin resets the ISL91302BIK buck output(s), set by DVS0, which reside in the BUCKx_DVS0CFG1 and BUCKx_DVS0CFG0 registers.



 t_{SLEW} is determined by the default output voltage divided by $3mV/\mu s$, while $t_{DEBOUNCE}$ is set at 10ms. $t_{DEBOUNCE}$ is factory programmable.



Figure 27. Watchdog Timer Example Case

5.10 Interrupt Pin

The ISL91302BIK can alert the host when a warning or a fault has occurred through an IRQ interrupt request signal with configurable masking options that is connected to a configurable interrupt (INT) pin. The interrupt pin can be programmed to be active high, active low, an open drain, or a CMOS output.



Figure 28. Interrupt Tree



6. **Protection Features (Faults)**

The ISL91302BIK has integrated Overcurrent (OC), Overvoltage (OV), Undervoltage (UV), and Over-Temperature (OT) protection features.

6.1 Over-Temperature Protection

The ISL91302BIK provides protection against over-temperature conditions. An over-temperature protection circuit continuously monitors the die temperature of the chip and raises a fault when the temperature exceeds a predefined limit programmed by Register <u>FLT_TEMPSHUTDN</u>. The ISL91302BIK also contains a programmable thermal warning threshold set by Register <u>FLT_TEMPWARN</u>. Programmable Hysteresis enables the circuit to clear the fault or warning once the temperature is below a user-defined safe temperature. The warning and shutdown hysteresis level are factory programmable. Contact Renesas <u>support</u> for custom settings. The over-temperature protection is disabled if all bucks are operating in PFM mode or in the off state.

6.2 Overcurrent Protection Mode

The ISL91302BIK has implemented a comparator-based OCP and an ADC-based OCP mechanism. The comparator based OCP or 'WOC' block has a current comparator, which compares the load current through the high-side power FET with the reference current level through a replica device. If the sensed FET current is higher than the WOC threshold, the WOC is triggered immediately, preventing a catastrophic condition. The WOC disables the buck and latches the power-stage into tri-state until the fault is cleared. The WOC fault is self-cleared when the OC condition is removed and the buck attempts to re-enable in a hiccup type fashion. The ADC based OCP monitors the averaged high-side and low-side MOSFET current for each phase and is slower but more accurate than the comparator based WOC. If the Buck total current is higher than the ADC based OCP threshold, the ADC OCP is triggered, which shutdowns the Buck and latches the power-stage into tri-state. ADC based OCP can only be cleared by recycling the PVIN/AVIN or by toggling the EN pin. Please note the ADC based OC cannot be cleared by toggling the IO_BUCKx_EN bit by I²C/SPI.

Overcurrent protection can be enabled or disabled using the fault register setting in FLT_BUCKx_CTRL. ADC based current warning and shutdown limits can be adjusted with the FLT_BUCKx_ISENSEWARN and FLT_BUCKx_ISENSESHUTDN registers, respectively.

6.3 Overvoltage (OV)/Undervoltage (UV) Protection

The ISL91302BIK protects against output overvoltage and undervoltage fault conditions. The OV/UV protection circuitry has low power comparators configured with differential input and single-ended outputs capable of working over large common-mode input ranges. This comparator is used to monitor the output voltage in both DCM and CCM for faults. By default, when an OV/UV event is triggered, the buck converter is shut down until the fault is cleared. Fault control register FLT_BUCKx_CTRL is used to enable or disable the functionality. The OV/UV limits are adjustable using the BUCKx_UVOVTH[1:0] bits in the BUCKx_PROTCFG register. See <u>Table 17</u> for more details.

| BUCKxUVOVTH[1:0] | OV/UV Threshold |
|------------------|--------------------------|
| 0x0 | ±150mV around DAC target |
| 0x1 | ±200mV around DAC target |
| 0x2 | ±250mV around DAC target |
| 0x3 | ±300mV around DAC target |

Table 17. OV/UV Protection Thresholds



7. Serial Communication Interface

The ISL91302BIK has two serial interface protocols to read/write the registers.

- SPI
- I²C



Figure 29. SPI and I²C Interface Block Diagram

The arbitration of the register access bus between SPI and I^2C is determined by the pad MPIO1 when using IO_PINMODE = 0x0, as shown in <u>Table 18</u>:

Table 18. SPI/I²C Register Access

| Register IO_PINMODE | Pad MPIO_1 (SS_B) | Register Access | | |
|---------------------|-------------------|--|--|--|
| 0 | 0 | SPI (Read/Write Access (<u>Note 11</u>)) | | |
| | 1 | I ² C (<u>Note 12</u>) | | |

Notes:

11. When the device is configured for SPI access, the I^2C should not be addressed with the device ID.

12. When the device is configured for I²C access, in PINMODE 0, the SS_B line must be held high.

After switching from SPI to I^2C or from I^2C to SPI, there is a minimum of 50ns wait time is required before starting a transaction.

7.1 SPI Serial Interface

The SPI interface is a general specification four-wire slave interface capable of operating at a clock speed of up to 26MHz. It is based on byte transfers.

7.1.1 SPI Data Protocol

Both Read and Write SPI transactions begin when SS_B goes low and end when SS_B goes high.

7.1.1.1 Write Operation

To write to the ISL91302BIK, the master (controller) needs to drive SS_B low and send the Control Byte, followed by the register address, packet length (if IO_SPIMODE = 1), Data bytes to be written, and finally drive SS_B high to terminate the transaction as shown below. The MSB of the Control byte is the R/W bit, which needs to be set to 'write' operation (see IO_SPIRWPOL). Bit 6, AI indicates if it is going to be a single-byte write operation or a multi-byte write. Bits 1 and 0 of the Control byte, indicate the page number of the register location desired to be written (MSBs of the register address). The register address byte is the 8-bit address of the register within the page specified by Page[1:0] bits. If IO_SPIMODE = 1, the register address needs to be followed by 8-bit packet length, which indicates the number of bytes to be written. Following the packet length field, the master needs to send the data bytes. When all eight bits of data are received, they get written to the specified register address and the ISL91302BIK increments the register address.

In single byte transactions, (AI = 0 or Packet length = 1), the ISL91302BIK goes into wait state and waits for SS_B to go high.



In multi-byte transactions with IO_SPIMODE = 1, the ISL91302BIK writes the subsequently received data bytes to sequentially incrementing addresses until the number of bytes, as specified by 'packet length', are received and then go into the wait state and wait for SS_B to go high. For multi-byte transactions with IO_SPIMODE = 0 and AI = 1, the ISL91302BIK keeps writing the subsequently received data bytes to sequentially incrementing addresses until SS_B goes high. If SS_B goes high in the middle of a transaction, the transaction is terminated. The data byte is written if all eight bits are received.



Figure 30. SPI Write Transaction with IO_SPIMODE = 1; IO_SPICPOL = 0; IO_SPICPHA = 0

7.1.1.2 Read Operation

To read from the ISL91302BIK, the master (controller) needs to drive SS_B low and then send the Control Byte, followed by register address, packet length (if IO_SPIMODE = 1). The ISL91302BIK then sends the data bytes from the requested registers and finally the master drives SS_B high to terminate the transaction. The MSB of the Control byte is the R/W bit which needs to be set to 'read' operation (see IO_SPIRWPOL). Bit 6, AI indicates if it is going to be a single-byte read operation or a multi-byte read. Bits 1 and 0 of the Control byte indicate the page number of the register location be read (MSBs of the register address). The register address byte is the 8-bit address of the register within the page specified by Page[1:0] bits. If IO_SPIMODE = 1, the register address needs to be followed by an 8-bit packet length, which indicates the number of bytes to be written. Following the packet length field, the ISL91302BIK sends the data from the requested register. When all eight bits of data from the requested register address.

In a single-byte transaction, (AI = 0 or Packet length = 1), the ISL91302BIK goes into a wait state and waits for SS_B to go high.

In a multi-byte transaction with IO_SPIMODE = 1, the ISL91302BIK sends the data bytes from sequentially incrementing addresses until the number of bytes as specified by 'packet length' are sent and then goes into a wait state and waits for SS_B to go high. For multi-byte transactions with IO_SPIMODE = 0 and AI = 1, the ISL91302BIK keeps sending data bytes from sequentially incrementing addresses until SS_B goes high.

Note: The MISO pin is pulled low while SS_B is high.



* Only present when IO_SPIMODE = 1 ^ Only present for Multi Word Transactions

Figure 31. SPI Read Transaction with IO_SPIMODE = 1; IO_SPICPOL = 0; IO_SPICPHA = 0



| R/W | Read/Write Bit Indicating Read or Write Operation |
|---------------|---|
| AI | Auto Increment. 1 indicates multi-byte transfer, 0 indicates single byte transfer |
| Page | 2-bit page address of the register to be written/read |
| Address | 8-bit register address of the register to be written/read |
| Packet Length | 8-bit packet length indicating number of data bytes to be transferred. Overrides AI when IO_SPIMODE = 1 |
| Read Data | Data in the register at address, Address [7:0] + n |
| Write Data | Data to be written to the register at address, Address [7:0] + n |

7.1.2 SPI Configuration

The following register bits configure the SPI operation:

- **IO_SPICPOL:** SPI clock polarity, ISL91302BIK is configured as active high, IO_SPICPOL = 0
- IO_SPICPHA: SPI clock phase, ISL91302BIK samples data on rising edge of SPI clock, IO_SPICPHA = 0

The four possible modes of clocking are shown in Figure 32.



Figure 32. Four Possible Clocking Modes

• **IO_SPIRWPOL**: R/W bit polarity, ISL91302BIK SPI_RWPOL is set to 0, 1: Read, 0: Write.

| SPI_RWPOL | R/W | Operation | | |
|-----------|-----|-----------|--|--|
| 0 | 0 | Write | | |
| 0 | 1 | Read | | |

• **IO_SPIMODE**: Packet length enable, the ISL91302BIK uses packet length mode by default, meaning the third data byte from master is the packet length and indicates the total number of data words to be sent/received in a burst transaction.



7.1.3 SPI Timing

<u>Figure 33</u> shows SPI timing for IO_SPICPOL = 0; IO_SPICPHA = 0. The timing values in <u>Tables 19</u> hold true for other values of IO_SPICPOL, IO_SPICHPA as well.

Table 19. Timing Values

| Parameter | Symbol | Min | Max | Units |
|--|----------------|------|-----|-------|
| Clock Period | t ₁ | 38.4 | | ns |
| Enable Lead Time | t ₂ | 12 | | ns |
| Enable Lag Time | t ₃ | 12 | | ns |
| Clock High or Low Time | t ₄ | 15 | | ns |
| Data Setup Time (Input) | t ₅ | 12 | | ns |
| Data Hold Time (Input) | t ₆ | 10 | | ns |
| Time MISO is Stable before the Next Rising Edge of CLK | t ₇ | 5 | | ns |
| Data Held after Clock Edge (Output) | t ₈ | 5 | | ns |
| Load Capacitance | CL | | 10 | pF |



Figure 33. SPI Timing for IO_SPICPHA = 0, IO_SPICPOL = 0

7.2 I²C Interface

The I²C interface is a simple, bidirectional 2-wire bus protocol, consisting of the Serial Clock Control (SCL/I2C_CLK) and the Serial Data Signal (SDA/I2C_SDA). The ISL91302BIK hosts a slave I²C interface that supports data speeds up to 3.4Mbps. SCL is an input to the ISL91302BIK and is supplied by the controller, whereas SDA is bidirectional. The ISL91302BIK has an open-drain output to transmit data on SDA. An external pull-up resistor must be placed on the serial data line to pull the drain output high during data transmission.

The ISL91302BIK uses a 7-bit hardware address scheme. The default address is set to 0x1D by a one-time programmable fuse.

7.2.1 I²C Bus Operation

The chip supports 7-bit addressing. The ISL91302BIK I²C device address is reconfigurable through the OTP.

All communication over the I²C interface is conducted by sending the MSB of each byte of data first. Data states on the SDA line can change only during SCL LOW periods. SDA state changes during SCL HIGH are reserved for indicating START and STOP conditions (see Figure 38).

All I²C interface operations must begin with a START condition, which is a HIGH to LOW transition of SDA while SCL is HIGH. The ISL91302BIK continuously monitors the SDA and SCL lines for the START condition and does not respond to any command until this condition is met. All I²C interface operations must be terminated by a STOP condition, which is a LOW to HIGH transition of SDA while SCL is HIGH.

An Acknowledge (or ACK), is a software convention used to indicate a successful data transfer. The transmitting device, either master or slave, releases the SDA bus after transmitting eight bits. During the ninth clock cycle, the receiver pulls the SDA line LOW to acknowledge the reception of the eight bits of data (Figure 38). The ISL91302BIK responds with an ACK after recognition of a START condition, followed by a valid Identification (also known as I²C Address) Byte. The ISL91302BIK also responds with an ACK after receiving a Data Byte of a write operation. The master must respond with an ACK after receiving a Data Byte of a read operation.



7.2.1.1 Write Operation

A Write operation requires a START condition, followed by an ISL91302BIK I²C Address byte with the R/W bit set to 0, a Register Address Byte, Data Bytes, and a STOP condition. After each byte, the ISL91302BIK responds with an ACK. After every data byte, the ISL91302BIK auto increments the register address so subsequent data bytes get written to sequentially incremental register locations. A STOP condition that terminates the write operation must be sent by the master after sending at least one full data byte and its associated ACK signal. If a STOP byte is issued in the middle of a data byte, then the write is not performed.



Figure 34. 1-Byte Write to Register M



Figure 35. L-Byte Sequential Data Write Starting Register M

7.2.1.2 Read Operation

A Read operation consists of a three-byte dummy write instruction to send the register address to begin reading from, followed by a Current Address Read operation. The master initiates the operation, issuing the following sequence: a START condition, followed by an ISL91302BIK I²C Address byte with the R/W bit set to 0, a Register Address Byte, a second START, and a second ISL91302BIK I²C Address byte with the R/W bit set to 1. After each of the three bytes, the ISL91302BIK responds with an ACK. The ISL91302BIK then transmits Data Bytes. The master terminates the Read operation from the ISL91302BIK by issuing a STOP condition following the last bit of the last data byte. After every data byte, the ISL91302BIK auto increments the register address so subsequent data bytes are sent from sequentially incremental register locations.



Figure 36. 1-Byte Data Read from Register M



Figure 37. L-Byte Sequential Data Read Starting Register M



7.2.2 I²C Timing

The timing specifications of the I²C I/O from the I²C spec are shown in <u>Figure 38</u> and <u>Table 20</u>. The I²C controller provides a slave I²C transceiver capable of interpreting I²C protocol in Standard, Fast, Fast+, and High Speed modes.



Figure 38. I²C Timing



Table 20. I²C Specification

| | | Standard Mode | | Fast Mode | | Fast Mode Plus | | High Speed Mode | | |
|---|----------------------|---------------|--------|--|--------|--|--------|----------------------|------|------|
| Parameter | Symbol | Min | Max | Min | Max | Min | Max | Min | Max | Unit |
| Clock Frequency | f _{SCL} | 0 | 100 | 0 | 400 | 0 | 1000 | 0 | 3400 | kHz |
| Hold Time (repeated) START Condition. (After this period, the first clock pulse is generated.) | t _{HD} ;STA | 4000 | - | 600 | - | 260 | - | 160 | - | ns |
| LOW Period of the SCL Clock | t _{LOW} | 4700 | - | 1300 | - | 500 | - | 160 | - | ns |
| HIGH Period of the SCL Clock | t _{HIGH} | 4000 | - | 600 | - | 260 | - | 60 | - | ns |
| Setup Time for a Repeated START Condition | t _{SU;STA} | 4700 | - | 600 | - | 260 | - | 160 | - | ns |
| Data Hold Time | t _{HD;DAT} | 15 | - | 15 | - | 15 | - | 15 | 70 | ns |
| Data Setup Time | t _{SU;DAT} | 250 | - | 100 | - | 50 | - | 10 | - | ns |
| Rise Time of SCL | t _{rCL} | - | 1000 | - | 300 | - | 120 | - | 40 | ns |
| Fall Time of SCL | t _{fCL} | - | 300 | - | 300 | - | 120 | - | 40 | ns |
| Rise Time of SDA | t _{rDA} | - | 1000 | 20 | 300 | - | 120 | 10 <u>Note 14</u> | 80 | ns |
| Fall Time of SDA | t _{fDA} | - | 300 | 20 × (V _{DD} /5.5V) <u>Note 13</u> | 300 | 20 × (V _{DD} /5.5V) <u>Note 13</u> | 120 | 10 <u>Note 14</u> | 80 | ns |
| Setup Time for STOP Condition | t _{SU;STO} | 4000 | - | 600 | - | 260 | - | 160 | - | ns |
| Bus Free Time between a STOP and START Condition | t _{BUF} | 4700 | - | 1300 | - | 500 | - | - | - | ns |
| Capacitive Load for each Bus Line | Cb | - | 400 | - | 400 | - | 400 | | 100 | pF |
| Output Fall Time from VIHmin to VILmax | t _{of} | - | 250[5] | 20 × (V _{DD} /5.5V)[6] | 250[5] | 20 × (V _{DD} /5.5V)[6] | 120[7] | 10 <u>Note 14</u> | 80 | ns |
| Pulse Width of Spikes Suppressed by the Input Filter | t _{SP} | - | - | 0 | 50 | 0 | 50 | 0 | 10 | ns |

Notes:

13. Valid only for V_{DD} < 4V.

14. Valid only for V_{DD} < 1.9V.

15. V_{DD} is the pull-up source to the I²C lines (GPIO0, GPIO1).

ISL91302BIK

8. Board Layout Recommendations

The ISL91302BIK is a high frequency multiphase switching regulator and the proper PCB layout is an important design practice to ensure a satisfactory performance. The power loop is composed of the output inductor L, the output capacitor C_{OUT} , the PH pin, and the PGND pin. It is important to make the power loop as small as possible and the connecting traces among them should be direct, short, and wide. The same practice should be applied to the connections of the PVIN pin, the input capacitor, and PGND. The switching node of the converter, the PH pin, and the traces connected to this node are very noisy, so keep the VOUT and RTN lines and other noise sensitive traces away from these traces. Place the input capacitors as close as possible to the PVIN(s) and PGND(s) pins. Connect the ground of the input and output capacitors as close as possible as well. In addition, a solid ground plane is helpful for a good EMI performance.

Inductor placement should also be as close to the phase pins as possible. Using wide traces and reducing the length helps to improve the overall efficiency and reduce the amount of radiated EMI. For the phase traces, Renesas recommends only descending one layer to reduce the effective path to the inductor. Ensure the length and width of each inductor trace and number of microvias used match to help ensure proper current sharing between phases.

Place an AVIN filter capacitor as close as possible to the AVIN_FILT pin but away from noise sources. Always reference the GND pad of the decoupling capacitor to a quiet GND plane.

Do not use plated through-holes when passing the BGA pins to lower layers. Renesas recommends to using microvias that are staggered if they are required to pass down multiple layers.

The VOUT and RTN lines are used to sense the output voltage and should be routed directly to the load. Connecting the RTN line to ground away from the load causes a ground error in the output voltage load regulation due to parasitic ground resistance. Keep these traces away from switching nodes, which could be a converter phase node or high-speed digital signals. The use of small low inductance capacitors at the load improves noise immunity and transient response to the ISL91302BIK.



Figure 39. Recommended PCB Layout Top Layer


Provide a solid ground plane in the adjacent layer to provide a low impedance path to support high current flow. Copper planes need to be parallel with the phase traces on the top layer to minimize resistance, and they must be surrounded by a GND plane to prevent noise coupling.



Figure 40. Recommended PCB Layout Second Layer

Feedback lines must be kept away from noise sources such as the switching node, inductor, and high-speed digital signals. Run the traces to cut through the surrounding ground plane areas to minimize noise pick up. Add ground planes above and below the signals when applicable.



Figure 41. Recommended PCB Layout Bottom Layer

8.1 PCB Layout Summary

- 1. Place input capacitors as close as possible to their respective PVIN and PGND pins.
- 2. Route phase nodes with short, wide traces, and avoid any sensitive nodes.
- 3. Route VOUT and RTN lines differentially to the load and use small low ESL capacitors at the load for bypassing.
- 4. Output capacitors should be close to the inductors and have a low impedance path to the PGND pins.
- 5. Keep digital and phase nodes from intersecting AVIN_FILT, VOUT, and RTN lines on adjacent layers.



8.2 PCB Design for TFBGA Recommendations

| Design Feature | Design Specification | | | | | | |
|------------------------------------|--|--|--|--|--|--|--|
| Cu Pad Diameter | 0.8mm pitch: 0.215 ±0.012mm | | | | | | |
| Microvia Structure | All microvias should be copper filled. | | | | | | |
| Microvia Stacking | Avoid microvia stacking if possible. Use staggered vias instead. If microvia stacking is absolutely necessary for the layout, the maximum number of recommended via stacks is two. | | | | | | |
| Plated Through-Hole (PTH) Location | No PTH should be placed under the BGA ball pads. Microvias and trace routing should be used to fan the PTH away from the BGA ball array. | | | | | | |



9. Register Address Map

When communicating with registers that contain reserved bits, it is recommended to do a masked write/read to avoid modifying sensitive register values.

| Address | Register | Address | Register | Address | Register |
|---------|-------------------|---------|-----------------|---------|------------------|
| 0x01 | IO_CHIPNAME | 0x2A | ADC_SAMPLE4TMSB | 0x77 | BUCK1_DVS2CFG0 |
| 0x13 | FLT_RECORDTEMP | 0x2B | ADC_SAMPLE4TLSB | 0x78 | BUCK1_DVS3CFG1 |
| 0x14 | FLT_RECORDBUCK1 | 0x2C | ADC_SAMPLE5MSB | 0x79 | BUCK1_DVS3CFG0 |
| 0x15 | FLT_RECORDBUCK2 | 0x2D | ADC_SAMPLE5LSB | 0x7D | BUCK1_DVSSEL |
| 0x16 | ADC_SAMPLE0MSB | 0x2E | ADC_SAMPLE6MSB | 0x7E | BUCK1_RSPCFG1 |
| 0x17 | ADC_SAMPLE0LSB | 0x2F | ADC_SAMPLE6LSB | 0x7F | BUCK1_RSPCFG0 |
| 0x18 | ADC_SAMPLE1PH1MSB | 0x30 | ADC_AUX0MSB | 0x80 | BUCK1_EN_DLY |
| 0x19 | ADC_SAMPLE1PH1LSB | 0x31 | ADC_AUX0LSB | 0x81 | BUCK1_SHUTDN_DLY |
| 0x1A | ADC_SAMPLE1PH2MSB | 0x32 | ADC_AUX1MSB | 0x82 | BUCK2_EA2 |
| 0x1B | ADC_SAMPLE1PH2LSB | 0x33 | ADC_AUX1LSB | 0x85 | BUCK2_DCM |
| 0x1C | ADC_SAMPLE1PH3MSB | 0043 | IO_SPICFG | 0x8E | BUCK2_DVS0CFG1 |
| 0x1D | ADC_SAMPLE1PH3LSB | 0x44 | IO_MODECTRL | 0x8F | BUCK2_DVS0CFG0 |
| 0x1E | ADC_SAMPLE1PH4MSB | 0x58 | FLT_TEMPWARN | 0x90 | BUCK2_DVS1CFG1 |
| 0x1F | ADC_SAMPLE1PH4LSB | 0x59 | FLT_TEMPSHUTDN | 0x91 | BUCK2_DVS1CFG0 |
| 0x20 | ADC_SAMPLE1TMSB | 0x60 | FLT_MASKTEMP | 0x92 | BUCK2_DVS2CFG1 |
| 0x21 | ADC_SAMPLE1TLSB | 0x61 | FLT_MASKBUCK1 | 0x93 | BUCK2_DVS2CFG0 |
| 0x22 | ADC_SAMPLE2MSB | 0x62 | FLT_MASKBUCK2 | 0x94 | BUCK2_DVS3CFG1 |
| 0x23 | ADC_SAMPLE2LSB | 0x66 | BUCK1_EA2 | 0x95 | BUCK2_DVS3CFG0 |
| 0x24 | ADC_SAMPLE3MSB | 0x69 | BUCK1_DCM | 0x99 | BUCK2_DVSSEL |
| 0x25 | ADC_SAMPLE3LSB | 0x72 | BUCK1_DVS0CFG1 | 0x9A | BUCK2_RSPCFG1 |
| 0x26 | ADC_SAMPLE4PH1MSB | 0x73 | BUCK1_DVS0CFG0 | 0x9B | BUCK2_RSPCFG0 |
| 0x27 | ADC_SAMPLE4PH1LSB | 0x74 | BUCK1_DVS1CFG1 | 0x9C | BUCK2_EN_DLY |
| 0x28 | ADC_SAMPLE4PH2MSB | 0x75 | BUCK1_DVS1CFG0 | 0x9D | BUCK2_SHUTDN_DLY |
| 0x29 | ADC_SAMPLE4PH2LSB | 0x76 | BUCK1_DVS2CFG1 | | |

Note: The registers not listed in the register map and RESERVED bits in the register map are reserved for factory use only. Changing these registers/bits can result in unexpected operation.



10. Register Description by Address

| Address | Bit | Name | R/W | Default | Description |
|----------|------------------|---------------|-----|---------|--|
| IO_CHIPN | AME | | | | |
| 0x01 | 7:0 | IO_CHIPNAME | R | 0x02 | Chip Name, Set by Renesas 0x02 ISL91302BIK, dual/single output PMIC |
| FLT_REC | ORD [.] | TEMP | | | |
| 0x13 | 7 | FLT_BOOT | R | 0x0 | BOOT Occurred |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No boot process has occurred since the last time this register was read. |
| | | | | | 0x1 Boot process has occurred (set high after OTP read is finished). |
| | 6:4 | Reserved | R | 0x0 | Reserved |
| | 3 | FLT_TEMPSDR | R | 0x0 | · · · · · · · · · · · · · · · · · · · |
| | | | | | Over-Temperature (OT) Shutdown (Rising Threshold) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 2 | FLT_TEMPWARNR | R | 0x0 | |
| | | | | | Over-Temperature (OT) Warning (Rising Threshold) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 1 | FLT_TEMPWARNF | R | 0x0 | Over-Temperature (OT) Warning (Falling Threshold) (Warning1 Hysteresis) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 0 | FLT_TEMPSDF | R | 0x0 | Over-Temperature (OT) Shutdown (Falling Edge) (Shutdown Hysteresis) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |



| Address | Bit | Name | R/W | Default | Description |
|-----------|-----|-----------------|-----|---------|---|
| FLT_REC | ORD | BUCK1 | | | |
| 0x14 | 7 | Reserved | R | 0x0 | Reserved |
| | 6 | FLT_BUCK1_WOC | R | 0x0 | |
| | | | | | Way Overcurrent (WOC) for Buck1 |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 5 | FLT_BUCK1_OV | R | 0x0 | Overvoltage (OV) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 4 | FLT_BUCK1_UV | R | 0x0 | |
| | 4 | | , r | 0.00 | Undervoltage (UV) |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, greater than threshold. |
| | | | | | 0x1 Fault, less than threshold |
| | 3 | FLT_BUCK1_OCSDR | R | 0x0 | |
| | - | | | | Overcurrent (OC) Shutdown (Rising Threshold) for Buck1 |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 2 | FLT_BUCK1_OCWR | R | 0x0 | Oversurrent (OC) Werping (Pising Threshold) for Pusk1 |
| | | | | | Overcurrent (OC) Warning (Rising Threshold) for Buck1 Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x0 No radit, ress than threshold. 0x1 Fault, greater than threshold. |
| | | | | | |
| | 1 | FLT_BUCK1_OCWF | R | 0x0 | Overcurrent (OC) Warning (Falling Threshold) Buck1 |
| | | | | | Read only, cleared when read |
| | | | | | 0x0 No fault, less than threshold. |
| | | | | | 0x1 Fault, greater than threshold. |
| | 0 | Reserved | R | 0x0 | Reserved |
| FLT_REC | ORD | | | | 1 |
| - 0x15 | 7 | Reserved | R | 0x0 | See <u>FLT_RECORDBUCK1</u> |
| | 6 | FLT_BUCK2_WOC | R | 0x0 | 1 |
| | 5 | FLT_BUCK2_OV | R | 0x0 | |
| | 4 | FLT_BUCK2_UV | R | 0x0 | |
| | 3 | FLT_BUCK2_OCSDR | R | 0x0 | |
| | 2 | FLT_BUCK2_OCWR | R | 0x0 | |
| | 1 | FLT_BUCK2_OCWF | R | 0x0 | |
| | 0 | Reserved | R | 0x0 | |



| Address | Bit | Name | R/W | Default | De | scription |
|---------|------|----------------|-----|---------|---|--|
| ADC_SAN | IPLE | 0MSB | | | | |
| 0x16 | 7:0 | ADC_SAMPLE0MSB | R | | Upper Byte of Temperature Sam (combine with LSB for 16-bit val | |
| | | | | | Source | Temp. Sensor |
| | | | | | Range | ±200 °C |
| | | | | | Format | s.13.2 |
| | | | | | Units | Temperature °C |
| | | | | | 0x0000 | 0 |
| | | | | | 0x0001 | 0.25 |
| | | | | | 0x0002 | 0.5 |
| | | | | | 0x0003 | 0.75 |
| | | | | | 0x0004 | 1 |
| | | | | | | |
| | | | | | 0x0010 | 4 |
| | | | | | | |
| | | | | | 0x0100 | 64 |
| | | | | | | |
| | | | | | 0x0320 | 200 |
| | | | | | 0xFCE0 | -200 |
| | | | | | 0xFCDF | -219.75 |
| | | | | | | |
| | | | | | 0xFFFF | -0.25 |
| ADC_SAM | IPLE | 0LSB | I | | | |
| 0x17 | 7:0 | ADC_SAMPLE0LSB | R | | Lower Byte of Temperature Sampl See <u>"ADC_SAMPLE0MSB"</u> for de | e (combine with MSB for 16-bit value) code. |



| Address | Bit | Name | R/W | Default | D | escription |
|---------|-------|-------------------|-----|---------|---|---|
| ADC_SAM | IPLE | 1PH1MSB | | | | |
| 0x18 | 7:0 | ADC_SAMPLE1PH1MSB | R | | Upper Byte of Buck1, Phase1 (combine with LSB for 16-bit v | |
| | | | | | Source | ISENSE |
| | | | | | Range | ±8.192A |
| | | | | | Format | s.13.2 |
| | | | | | Units | Current (mA) |
| | | | | | 0x0000 | 0 |
| | | | | | 0x0001 | 0.25 |
| | | | | | 0x0002 | 0.5 |
| | | | | | 0x0003 | 0.75 |
| | | | | | 0x0004 | 1 |
| | | | | | | |
| | | | | | 0x0010 | 4 |
| | | | | | | |
| | | | | | 0x0100 | 64 |
| | | | | | | |
| | | | | | 0x7FFF | 8191.75 |
| | | | | | 0x8000 | -8192 |
| | | | | | 0x8001 | -8191.75 |
| | | | | | | |
| | | | | | 0xFFFF | -0.25 |
| ADC_SAM | /IPLE | 1PH1LSB | | | | |
| 0x19 | 7:0 | ADC_SAMPLE1PH1LSB | R | | Lower Byte of Buck1, Phase1 Ouvalue) See <u>"ADC_SAMPLE1PH1</u> | Itput Current (combine with MSB for 16-bit |
| ADC_SAM | IPLE | 1PH2MSB | | | | |
| 0x1A | 7:0 | ADC_SAMPLE1PH2MSB | R | | Upper Byte of Buck1, Phase2 Ouvalue.) See <u>"ADC_SAMPLE1PH</u> | utput Current (combine with LSB for 16-bit <u>1MSB</u> [*] for decode. |
| ADC_SAM | IPLE | 1PH2LSB | | | | |
| 0x1B | 7:0 | ADC_SAMPLE1PH2LSB | R | | Lower Byte of Buck1, Phase2 Ou value) See <u>"ADC_SAMPLE1PH1</u> | tput Current (combine with MSB for 16-bit MSB [*] for decode. |
| ADC_SAM | IPLE | 1PH3MSB | | | | |
| 0x1C | 7:0 | ADC_SAMPLE1PH3MSB | R | | Upper Byte of Buck1, Phase3 Ou value.) See <u>"ADC_SAMPLE1PH</u> | utput Current (combine with LSB for 16-bit <u>1MSB</u> [*] for decode. |
| ADC_SAM | IPLE | 1PH3LSB | | | | |
| 0x1D | 7:0 | ADC_SAMPLE1PH3LSB | R | | Lower Byte of Buck1, Phase3 Ou value) See <u>"ADC_SAMPLE1PH1</u> | tput Current (combine with MSB for 16-bit MSB [*] for decode. |
| ADC_SAM | IPLE | 1PH4MSB | | | | |
| 0x1E | 7:0 | ADC_SAMPLE1PH4MSB | R | | Upper Byte of Buck1, Phase4 Ou value.) See <u>"ADC_SAMPLE1PH</u> | utput Current (combine with LSB for 16-bit <u>1MSB</u> [*] for decode. |
| ADC_SAM | IPLE | 1PH4LSB | | I | | |
| 0x1F | 7:0 | ADC_SAMPLE1PH4LSB | R | | Lower Byte of Buck1, Phase4 Ouvalue) See <u>"ADC_SAMPLE1PH1</u> | tput Current (combine with MSB for 16-bit |



| Address | Bit | Name | R/W | Default | Des | scription |
|---------|-------|-----------------|-----|---------|--|--|
| ADC_SAM | IPLE | 1TMSB | | L L | | |
| 0x20 | 7:0 | ADC_SAMPLE1TMSB | R | | Upper Byte of Buck1, Total Outp (Combine with LSB for 16-bit val | ut Current Reading ue.) |
| | | | | | Source | I _{SENSE} |
| | | | | | Range | ±32.768A |
| | | | | | Format | s.15 |
| | | | | | Units | Current (mA) |
| | | | | | 0x0000 | 0 |
| | | | | | 0x0001 | 1 |
| | | | | | 0x0002 | 2 |
| | | | | | 0x0003 | 3 |
| | | | | | 0x0004 | 4 |
| | | | | | | |
| | | | | | 0x0010 | 16 |
| | | | | | | |
| | | | | | 0x0100 | 256 |
| | | | | | | |
| | | | | | 0x7FFF | 32767 |
| | | | | | 0x8000 | -32768 |
| | | | | | 0x8001 | -32767 |
| | | | | | | |
| | | | | | 0xFFFF | -1 |
| ADC_SAN | /IPLE | 1TLSB | I | | | |
| 0x21 | 7:0 | ADC_SAMPLE1TLSB | R | | Lower Byte of Buck1, Total Output 16-bit value) See <u>"ADC_SAMPLE1</u> | Current Reading (combine with MSB f TMSB" for decode. |



| Address | Bit | Name | R/W | Default | Des | cription |
|---------|-------------------------|----------------|-----|---|---|---|
| ADC_SAM | IPLE | 2MSB | | | | |
| 0x22 | 0x22 7:0 ADC_SAMPLE2MSB | R | | Upper Byte of Buck1, PVIN Sam (combine with LSB for 16-bit value | | |
| | | | | | Source | PVIN |
| | | | | | Range | ±8.192V |
| | | | | | Format | s.13.2 |
| | | | | | Units | Voltage (mV) |
| | | | | | 0x0000 | 0 |
| | | | | | 0x0001 | 0.25 |
| | | | | | 0x0002 | 0.5 |
| | | | | | 0x0003 | 0.75 |
| | | | | | 0x0004 | 1 |
| | | | | | | |
| | | | | | 0x0010 | 4 |
| | | | | | | |
| | | | | | 0x0100 | 64 |
| | | | | | | |
| | | | | | 0x7FFF | 8191.75 |
| | | | | | 0x8000 | -8192 |
| | | | | | 0x8001 | -8191.75 |
| | | | | | | |
| | | | | | 0xFFFF | -0.25 |
| ADC_SAM | IPLE | 2LSB | 1 | | | |
| 0x23 | 7:0 | ADC_SAMPLE2LSB | R | | Lower Byte of Buck1 PVIN Reading See <u>"ADC_SAMPLE2MSB"</u> for dec | g (combine with MSB for 16-bit value) ode. |



| Address | Bit | Name | R/W | Default | | Description |
|---------|-------|-------------------|-----|---------|---|--|
| ADC_SAM | IPLE | 3MSB | | | | |
| 0x24 | 7:0 | ADC_SAMPLE3MSB | R | | Upper Byte of Buck1, V _{OUT} (combine with LSB for 16-bit | |
| | | | | | Source | V _{OUT} |
| | | | | | Range | ±8.192V |
| | | | | | Format | s.13.2 |
| | | | | | Units | Voltage (mV) |
| | | | | | 0x0000 | 0 |
| | | | | | 0x0001 | 0.25 |
| | | | | | 0x0002 | 0.5 |
| | | | | | 0x0003 | 0.75 |
| | | | | | 0x0004 | 1 |
| | | | | | | |
| | | | | | 0x0010 | 4 |
| | | | | | | |
| | | | | | 0x0100 | 64 |
| | | | | | | |
| | | | | | 0x7FFF | 8191.75 |
| | | | | | 0x8000 | -8192 |
| | | | | | 0x8001 | -8191.75 |
| | | | | | | |
| | | | | | 0xFFFF | -0.25 |
| ADC_SAM | /IPLE | 3LSB | | | | |
| 0x25 | 7:0 | ADC_SAMPLE3LSB | R | | Lower Byte of Buck1 V _{OUT} Rea See <u>"ADC_SAMPLE3MSB"</u> for | ding (combine with MSB for 16-bit value) decode. |
| ADC_SAM | IPLE | 4PH1MSB | | | | |
| 0x26 | 7:0 | ADC_SAMPLE4PH1MSB | R | | Upper Byte of Buck2, Phase1 C value) See <u>ADC_SAMPLE1PH</u> : | Dutput Current (combine with LSB for 16-bi 1MSB for decode. |
| ADC_SAM | IPLE | 4PH1LSB | • | | | |
| 0x27 | 7:0 | ADC_SAMPLE4PH1LSB | R | | Lower Byte of Buck2, Phase1 O value) See <u>ADC_SAMPLE1PH</u> | Output Current (combine with MSB for 16-bi 1MSB for decode. |
| ADC_SAM | IPLE | 4PH2MSB | | | | |
| 0x28 | 7:0 | ADC_SAMPLE4PH2MSB | R | | Upper Byte of Buck2, Phase2 C value) See <u>ADC_SAMPLE1PH</u> | Dutput Current (combine with LSB for 16-bi 1MSB for decode. |
| ADC_SAM | /IPLE | 4PH2LSB | | | | |
| 0x29 | 7:0 | ADC_SAMPLE4PH2LSB | R | | Lower Byte of Buck2, Phase2 O value) See <u>ADC_SAMPLE1PH</u> | Output Current (combine with MSB for 16-bi 1MSB for decode. |
| ADC_SAM | PLE | 4TMSB | | | | |
| 0x2A | 7:0 | ADC_SAMPLE4TMSB | R | | Upper Byte of Buck2, Total Outport Value) See <u>ADC_SAMPLE1TM</u> | put Current (combine with LSB for 16-bit <u>SB</u> for decode. |
| ADC_SAM | IPLE | 4TLSB | 1 | | | |
| 0x2B | 7:0 | ADC_SAMPLE4TLSB | R | | Lower Byte of Buck2, Total Outport | put Current (combine with MSB for 16-bit |



| Address | Bit | Name | R/W | Default | Descri | ption |
|---------|-------|----------------|--------|---------|---|------------------------------------|
| ADC_SAN | IPLE | 5MSB | | | | |
| 0x2C | 7:0 | ADC_SAMPLE5MSB | R | | Upper Byte of Buck2, PVIN Reading (See <u>ADC_SAMPLE2MSB</u> for decode. | |
| ADC_SAN | IPLE | 5LSB | | | | |
| 0x2D | 7:0 | ADC_SAMPLE5LSB | R | | Lower Byte of Buck2, PVIN Reading (See <u>ADC_SAMPLE2MSB</u> for decode. | |
| ADC_SAN | IPLE | 6MSB | | | | |
| 0x2E | 7:0 | ADC_SAMPLE6MSB | R | | Upper Byte of Buck2, V _{OUT} Reading (See <u>ADC_SAMPLE3MSB</u> for decode. | |
| ADC_SAN | IPLE | 6LSB | | | | |
| 0x2F | 7:0 | ADC_SAMPLE6LSB | R | | Lower Byte of Buck2, V _{OUT} Reading (See <u>ADC_SAMPLE3MSB</u> for decode. | combine with MSB for 16-bit value) |
| ADC_AUX | OMS | В | | | | |
| 0x30 | 7:0 | ADC_AUX0MSB | R | | Upper Byte of ADC Auxiliary Input # Can be used in IO_PINMODE = 0xC with internal ADC. | |
| | | | | | Source | AUX0 |
| | | | | | Range | ±8.192V |
| | | | | Format | s.13.2 | |
| | | | | Units | Voltage (mV) | |
| | | | | 0x0000 | 0 | |
| | | | 0x0001 | 0.25 | | |
| | | | | | 0x0002 | 0.5 |
| | | | | | 0x0003 | 0.75 |
| | | | | | 0x0004 | 1 |
| | | | | | | |
| | | | | | 0x0010 | 4 |
| | | | | | | |
| | | | | | 0x0100 | 64 |
| | | | | | | |
| | | | | | 0x7FFF | 8191.75 |
| | | | | | 0x8000 | -8192 |
| | | | | | 0x8001 | -8191.75 |
| | | | | | | |
| | | | | | 0xFFFF | -0.25 |
| ADC_AUX | OLSE | 3 | | | | |
| 0x31 | 7:0 | ADC_AUX0LSB | R | | Lower Byte of ADC Auxiliary Input #1 (See <u>"ADC_AUX0MSB"</u> for decode. | combine with MSB for 16-bit value |
| ADC_AUX | (1MS | В | | 1 | | |
| 0x32 | 7:0 | ADC_AUX1MSB | R | | Upper Byte of ADC Auxiliary Input #2 (Can be used in IO_PINMODE[3:0] = 0. with internal ADC. See <u>"ADC_AUX0M</u> : | xC, 0xD to measure external voltag |
| ADC_AUX | (1LSI | 3 | | • | | |
| 0x33 | 7:0 | ADC_AUX1LSB | R | | Lower Byte of ADC Auxiliary Input #2 (See <u>"ADC_AUX0MSB"</u> for decode. | combine with MSB for 16-bit value |



ISL91302BIK

| Address | Bit | Name | R/W | Default | Description |
|----------|-----|-----------------|-----|---------|---|
| IO_SPICF | G | | | | |
| 0x43 | 7 | IO_I2C_SPEED | R/W | 0x0 | I ² C Speed Control 0x0 Low speed glitch and slew filters by default, high speed filters selectable by bus command. |
| | | | | | 0x1 Glitch and slew filters set for high speed 3.4MHz mode. |
| | 6 | IO_SDA_SLEWFLTR | R/W | 0x0 | Transmit Slew Rate Control for I ² C SDA 0x0 Disabled slew filtering. 0x1 Enable slew filtering. |
| | 5 | IO_SPIRWPOL | R/W | 0x0 | R/W Polarity 0x0 R/W 1: Read, 0: Write 0x1 R/W 1: Write, 0: Read |
| | 4 | IO_IRQ_CMOS | R/W | 0x1 | IRQ Type 0x0 Open-drain output 0x1 CMOS output |
| | 3 | IO_IRQ_INVERT | R/W | 0x1 | IRQ Polarity 0x0 Active High 0x1 Active Low |
| | 2 | IO_SPICPOL | R/W | 0x0 | SPI Clock Polarity 0x0 Active High 0x1 Active Low |
| | 1 | IO_SPICPHA | R/W | 0x0 | SPI Clock Phase 0x0 Sample on the leading (first) clock edge Note: Data must be stable for a half cycle before the first clock cycle. 0x1 Sample on the trailing (second) clock edge, regardless of whether that clock edge is rising or falling. |
| | 0 | IO_SPIMODE | R/W | 0x1 | SPI Mode Selection0x0Byte Mode Command ByteR/W, AINC, 0x0, 0x0, 0x0, 0x0, P1, P0 Address ByteAddress ByteA7, A6, A5, A4, A3, A2, A1, A0 Data ByteD7, D6, D5, D4, D3, D2, D1, D00x1Byte Mode with Packet Length Field Command ByteR/W, AINC, 0x0, 0x0, 0x0, 0x0, 0x0, P1, P0 Address ByteAddress ByteA7, A6, A5, A4, A3, A2, A1, A0 Packet Length Byte L7, L6, L5, L4, L3, L2, L1, L0 Data ByteD7, D6, D5, D4, D3, D2, D1, D0 |



| Address | Bit | Name | R/W | Default | Description |
|---------|-----|------------------|-----|---------|--|
| IO_MODE | CTR | L | | | |
| 0x44 | 7 | IO_BUCK1_EN | R/W | 0x1 | Enable for Buck1 0x0 Buck1 disabled. 0x1 Buck1 enabled. |
| | 6 | IO_BUCK2_EN | R/W | 0x1 | Enable for Buck2 0x0 Buck2 disabled. 0x1 Buck2 enabled. |
| | 5:3 | RSVD | R | 0x0 | Reserved |
| | 2 | IO_ENVPPPULLDOWN | R/W | 0x1 | Enable for weak Pull-down on EN/VPP Pin 0x0 Weak pull-down disabled. 0x1 Weak pull-down enabled. |
| | 1 | RSVD | R/W | 0x0 | Reserved |
| | 0 | RSVD | R/W | 0x0 | Reserved |
| FLT_TEM | PWA | RN | | | |
| 0x58 | r | FLT_TEMPWARN | R/W | 0x55 | Temperature Warning Threshold (highest) °C = FLT_TEMPWARN[7:0] (Range 0°C to +255°C) 0x00 0 0x01 1 0x7F 0x80 128 0x81 129 0x8C 0x8C 140 0xFF 0xFF 255 |



| FLT_TEMPSHUTDN RW 0x8C Temperature Shutdown threshold (highest) 0x59 7.0 FLT_TEMPSHUTDN RW 0x8C Imperature Shutdown threshold (highest) 0x00 0 0 0 0 0 0x01 1 0x7F 127 0 0x80 128 0x8C 140 0x8C 0x81 129 0x8C 140 129 129 120 120 120 120 120 120 120 120 120 120 <td< th=""><th colspan="4">Description</th></td<> | Description | | | | | | |
|---|-------------------|--|--|--|--|--|--|
| 0x59 7:0 FLT_TEMPSHUTDN R/W 0x8C Temperature Shutdown threshold (highest) 0x59 7:0 FLT_TEMPSHUTDN R/W 0x8C *C = FLT_TEMPSHUTDN[7:0] (Range of 0x00 0 0x01 1 0x01 1 0x02 128 0x8E 7:4 FLT_BUCK1_ISENSEWARN 0x5B 7:4 FLT_BUCK1_ISENSEWARN R/W 0x5 Buck1 Current Sense Warning Rising Threshold 1 Hysteresis must be 2 0mA and smail enough to current goes below the failing threshold. 0x5B 7:4 FLT_BUCK1_ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold 1 IsenseWarning R/W 0x5 Buck1 Current Sense Warning Filling threshold. 0x0 0 0x1 510 <t< td=""><td colspan="7"></td></t<> | | | | | | | |
| Image: Second State | | | | | | | |
| 0x00 0 0x01 1 0x1 127 0x80 128 0x81 129 0x6C 0x6C 140 0x6C 0x58 7.4 FLT_BUCK1_ISENSEWARN R/W 0x58 7.4 ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis mat = 512mA* (FLT_BUCK1_ISENSEW Note: Hysteresis must be 20mA and small enough to current goes below the falling threshold. Current (mA) = 512mA* FLT_BUCK1_ISEN 0x4 2048 0x7 0x6 8160 3:0 FLT_BUCK1_sis | | | | | | | |
| 0x01 1 0x7F 127 0x80 128 0x81 129 0x81 129 0x86 140 0x86 140 0x7F 255 FLT_BUCK1_ISENSEWARN 0x86 0x5B 7.4 FLT_BUCK1_ ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis mat = 512mA* (FLT_BUCK1_ISENSEW) Note: Hysteresis must be ≥ 0mA and small enough to current goes below the falling threshold. Current (mA) = 512mA* FLT_BUCK1_ISENSEW) Note: Hysteresis must be ≥ 0mA and small enough to current (mA) = 512mA* FLT_BUCK1_ISENSEW) Note: Hysteresis must be ≥ 0mA and small enough to current (mA) = 512mA* FLT_BUCK1_ISENSEW) 0x0 0 0 0 0x1 510 0 0 0x4 2048 0 0 0x6 8160 0 0 0x6 8160 0 0 0x1 510 0 0 0x1 510 0 0 | ge 0°C to +255°C) | | | | | | |
| Image: Second | | | | | | | |
| 0x7F 127 0x80 128 0x81 129 0x8C 0x8C 140 0x8C 0x7F 255 FLT_BUCK1_ISENSEWARN 0x5B 0x5B 7.4 FLT_BUCK1_ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis must be 2 0mÅ and small enough to current goes below the failing threshold. Current (mA) = 512mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0x4 2048 0x4 2048 0xF 8160 0x0 0 0x1 510m. 0x0 | | | | | | | |
| Image: Constraint of the second sec | | | | | | | |
| 0x81 129 0x8C 140 0x8C 140 0xFF 255 FLT_BUCK1_ISENSEWARN 0xFF 255 Øx5B 7.4 FLT_BUCK1_ ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis must be 20mA and small enough to current goes below the falling threshold. 0x00 0 | | | | | | | |
| Image: Constraint of the second sec | | | | | | | |
| Image: Constraint of the second sec | | | | | | | |
| FLT_BUCK1_ISENSEWARN R/W 0x5 Buck1 Current Sense Warning Rising Threshold 0x58 7:4 FLT_BUCK1_ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold 0x58 7:4 FLT_BUCK1_ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold 0x58 7:4 FLT_BUCK1_ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold 0x1 510 Current (mA) = 512mA * FLT_BUCK1_ISEN 0x0 0 0x4 2048 Current (mA) = 510mA * FLT_BUCK1_ISEN 0x4 Buck1 Current Sense Warning Falling Threshold 0x7 8160 Current (mA) = 510mA * FLT_BUCK1_ISEN 0x4 Disense Warning Falling Threshold | | | | | | | |
| FLT_BUCK1_ISENSEWARN 0x5B 7:4 FLT_BUCK1_ ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis mA = 512mA * (FLT_BUCK1_ISENSEAW Note: Hysteresis must be 2 0mA and small enough to current goes below the falling threshold. 0x1 510 0x4 2048 0x5 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current (mA) = 510mA * FLT_BUCK1_ISEN 0x7 0x1 510 0x1 0x4 2048 0x4 0x5 8160 0x1 0x1 510mA * FLT_BUCK1_ ISENSEWARNF R/W 0x4 | | | | | | | |
| FLT_BUCK1_ISENSEWARN 0x5B 7:4 FLT_BUCK1_ISENSEWARNR 0x5B 0x5 Buck1 Current Sense Warning Rising Threshold 0x60 0 0 0x7 510 0x0 0x1 510 0x1 0x6 8160 0x4 0x7 8160 0x0 0x0 0 0 0x1 510mA* FLT_BUCK1_ISEN 0x6 0 0x4 0x7 8160 0x0 0x0 0 0x1 0x0 0 0x1 0x0 0 0x1 0x0 0 0x0 0x0 0 0x1 | | | | | | | |
| 0x5B 7:4 FLT_BUCK1_ ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis mA = 512mA* (FLT_BUCK1_ISENSEAW FLT_BUCK1_ISENSEAW Note: Hysteresis must be ≥ 0mA and small enough to current goes below the falling threshold. Current (mA) = 512mA* FLT_BUCK1_ISEN 0x0 Current (mA) = 512mA* FLT_BUCK1_ISEN 0x1 510 0x4 2048 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current (mA) = 510mA* FLT_BUCK1_ISEN 0x0 0 0x1 510 0xF 0x1 510 0x4 0x5 8160 | | | | | | | |
| 0x5B 7:4 FLT_BUCK1_ ISENSEWARNR R/W 0x5 Buck1 Current Sense Warning Rising Threshold Hysteresis mA = 512mA* (FLT_BUCK1_ISENSEAW FLT_BUCK1_ISENSEAW Note: Hysteresis must be ≥ 0mA and small enough to current goes below the falling threshold. Current (mA) = 512mA* FLT_BUCK1_ISEN 0x0 0 0x1 510 0x4 2048 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current (mA) = 510mA* FLT_BUCK1_ISEN 0x0 0 0 0x1 510 0x7 8160 | | | | | | | |
| ISENSEWARNR Buck1 Current Sense Warning Rising Threshold Hysteresis mA = 512mA * (FLT_BUCK1_ISENSEAW FLT_BUCK1_ISENSEAW Note: Hysteresis must be ≥ 0mA and small enough to current goes below the falling threshold. Ox1 512mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0x4 0x4 2048 0xF 8160 Current (mA) = 510mA * FLT_BUCK1_ISEN 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold Current (mA) = 510mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0xF 0x1 510mA * FLT_BUCK1_ISEN | | | | | | | |
| FLT_BUCK1_ISENSEAW Note: Hysteresis must be ≥ 0mA and small enough to current goes below the falling threshold. Current (mA) = 512mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0x4 2048 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold Current (mA) = 510mA * FLT_BUCK1_ISEN 0x0 0 0x4 | | | | | | | |
| Note: Hysteresis must be ≥ 0mĀ and small enough to current goes below the falling threshold. Current (mA) = 512mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0x4 2048 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold Current (mA) = 510mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 0x0 0x1 510mA * FLT_BUCK1_ISEN 0x4 510mA * FLT_BUCK1_ISEN 0x1 510 0x0 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 0x4 0x1 5100 0x4 2048 0xF 8160 0x0 0 0xF 8160 0x1 510mA*FLT_BUCK1_ISEN 0xF 8160 0x1 510mA*FLT_BUCK1_ISEN 0x4 0x5 8160 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 0x4 0x4 2048 0x4 2048 0xF 8160 8160 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0x1 510 0x0 0 0x1 510 0x0 0 0x1 510 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 0x4 0x4 2048 0xF 8160 0x6 0x6 0x7 510 0x8 0x7 8160 0x0 0 0x0 0 0x0 0 | SENSEWARNR | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 2048 0xF 8160 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0xx0 0 0x0 0 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 2048 0xF 8160 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0xx0 0 0x0 0 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 2048 0xF 8160 0xF 8160 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0x0 0 0x1 510mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0x0 0 0x1 510mA * FLT_BUCK1_ISEN | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0x0 0 0x1 510mA * FLT_BUCK1_ISEN 0x1 510 | | | | | | | |
| 3:0 FLT_BUCK1_ ISENSEWARNF R/W 0x4 Buck1 Current Sense Warning Falling Threshold 0x0 0 0x1 510mA * FLT_BUCK1_ISEN 0x1 510 | | | | | | | |
| ISENSEWARNF Buck1 Current Sense Warning Falling Threshold Current (mA) = 510mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 | | | | | | | |
| Current (mA) = 510mA * FLT_BUCK1_ISEN 0x0 0 0x1 510 | ł | | | | | | |
| 0x0 0 0x1 510 | | | | | | | |
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| | | | | | | | |
| 0xF 8160 | | | | | | | |
| FLT_BUCK2_ISENSEWARN | J | | | | | | |
| Ox5C 7:4 FLT_BUCK2_ R/W 0x5 Buck2 Current Sense Warning Rising Threshold | | | | | | | |
| INW INW <td></td> | | | | | | | |
| 3:0 FLT_BUCK2_ R/W 0x4 Buck2 Current Sense Warning Falling Threshold See <u>"FLT_BUCK1_ISENSEWARNF"</u> for decode. | | | | | | | |



10. Register Description by Address

| Address | Bit | Name | R/W | Default | Description | |
|---------|------|----------------------------|----------|---------|--|---|
| FLT_BUC | K1_I | SENSESHUTDN | | | | |
| 0x5D | 7:0 | FLT_BUCK1_ ISENSESHUTDN | R/W | 0xA0 | Buck1 Current Sense Shutdown Threshold (highest) Note: Hysteresis is accomplished by shutting down the Buck and | |
| | | | | | resetting the filtered I _{SENSE} value. | |
| | | | | | Current (mA) = 32mA * FLT_BUCK1_ISENSESHUTDN[7:0] | 1 |
| | | | | | 0x00 0 | |
| | | | | | 0x01 32 * Nph | |
| | | | | | | |
| | | | | | 0x7F 4064 * Nph | |
| | | | | | 0x80 4096 * Nph | |
| | | | | | 0x81 4128 * Nph | |
| | | | | | | |
| | | | | | 0xA0 5120 * Nph | |
| | | | | | | |
| | | | | | 0xFF 8160 * Nph (via ENCF) | |
| FLT_BUC | K2_I | SENSESHUTDN | <u> </u> | I | | |
| 0x5E | 7:0 | FLT_BUCK2_ ISENSESHUTDN | R/W | 0xA0 | Buck2 Current Sense Shutdown Threshold (Highest) See <u>"FLT_BUCK1_ISENSESHUTDN"</u> for decode. | |



| Address | Bit | Name | R/W | Default | Description | | | |
|---------|-----|-------------------|-----|---------|--|--|--|--|
| FLT_MAS | KTE | MP | | | | | | |
| 0x60 | 7 | FLT_MASKBOOT | R/W | 0x0 | Mask IRQ for FLT_BOOT | | | |
| | | | | | 0x0 IRQ passed to output pin. | | | |
| | | | | | 0x1 IQ masked from output pin. | | | |
| | | | | | | | | |
| | 6:4 | Reserved | R | 0x0 | Reserved | | | |
| | 3 | FLT_MASKTEMPSDR | R/W | 0x0 | Mask IRQ for FLT_TEMPSDR | | | |
| | | | | | 0x0 IRQ passed to output pin. | | | |
| | | | | | 0x1 IRQ masked from output pin. | | | |
| | 2 | FLT_MASKTEMPWARNR | R/W | 0x0 | Mask IRQ for FLT_TEMPWARNR | | | |
| | | | | | 0x0 IRQ passed to output pin Note: FLT_MASKTEMPWARNF must also be set to 0x0. Otherwise the IRQ clears itself when the temperature drops below the falling threshold. | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 1 | FLT_MASKTEMPWARNF | R/W | 0x0 | Mask IRQ for FLT_TEMPWARNF | | | |
| | | | | | 0x0 IRQ passed to output pin Note: FLT_MASKTEMPWARNR must also be set to 0x0. Otherwise the IRQ clears itself when the temperature goes above the rising threshold. | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 0 | FLT_MASKTEMPSDF | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_TEMPSDF | | | |
| | | | | | 0x0 IRQ passed to output pin. | | | |
| | | | | | 0x1 IQ masked from output pin. | | | |



| Address | Bit | Name | R/W | Default | Description | | | |
|---------|-----|---------------------|------------------|---------|---|--|--|--|
| FLT_MAS | KBU | CK1 | | | | | | |
| 0x61 | 7 | Reserved | d R 0x0 Reserved | | | | | |
| | 6 | FLT_BUCK1_MASKWOC | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_WOC | | | |
| | | | | | 0x0 IRQ passed to output pin | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 5 | FLT_BUCK1_MASKOV | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_OV | | | |
| | | | | | 0x0 IRQ passed to output pin | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 4 | FLT_BUCK1_MASKUV | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_UV | | | |
| | | | | | 0x0 IRQ passed to output pin | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 3 | FLT_BUCK1_MASKOCSDR | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_OCSDR | | | |
| | | | | | 0x0 IRQ passed to output pin | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 2 | FLT_BUCK1_MASKOCWR | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_OCWR | | | |
| | | | | | 0x0 IRQ passed to output pin Note: FLT_MASKOCWF must also be set to 0x0. Otherwise the IRQ clears itself when the current drops below the falling threshold. | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 1 | FLT_BUCK1_MASKOCWF | R/W | 0x0 | | | | |
| | | | | | Mask IRQ for FLT_BUCK1_OCWF | | | |
| | | | | | 0x0 IRQ passed to output pin | | | |
| | | | | | 0x1 IRQ masked from output pin | | | |
| | 0 | Reserved | R | 0x0 | Reserved | | | |



| Address | Bit | Name | R/W | Default | t Description | | | | |
|---------|-----|-----------------------|-----|---------|--|--|--|--|--|
| FLT_MAS | KBU | СК2 | 1 | | | | | | |
| 0x62 | 7 | FLT_BUCK2_MASKRSVD1 | R | 0x0 | IRQ Masks for Buck2 | | | | |
| | 6 | FLT_BUCK2_MASKWOC | R/W | 0x0 | See <u>"FLT_MASKBUCK1"</u> for description. | | | | |
| | 5 | FLT_BUCK2_MASKOV | R/W | 0x0 | | | | | |
| | 4 | FLT_BUCK2_MASKUV | R/W | 0x0 | | | | | |
| | 3 | FLT_BUCK2_MASKOCSDR | R/W | 0x0 | | | | | |
| | 2 | FLT_BUCK2_MASKOCWR | R/W | 0x0 | | | | | |
| | 1 | FLT_BUCK2_MASKOCWF | R/W | 0x0 | | | | | |
| | 0 | FLT_BUCK2_MASKRSVD2 | R | 0x0 | | | | | |
| BUCK1_E | A2 | | 1 | | | | | | |
| 0x66 | 7:6 | BUCK1_VOUTFBDIV | R/W | 0x0 | | | | | |
| | | | | | Feedback Divider Maximum V _{OUT} Setting | | | | |
| | | | | | 0x0 1.2000V | | | | |
| | | | | | 0x1 1.5000V | | | | |
| | | | | | 0x2 2.0000V | | | | |
| | | | | | 0x3 Reserved | | | | |
| | | Reserved | R | 0x1B | Reserved | | | | |
| BUCK1_D | СМ | | 1 | | | | | | |
| 0x69 | 7:3 | Reserved | N/A | 0x0 | Reserved | | | | |
| | 2 | BUCK1_FCCM | R/W | 0x0 | | | | | |
| | | | | | Forced Continuous Conduction Mode | | | | |
| | | | | | 0x0 Discontinuous Conduction Mode (DCM) allowed when load reaches 0A. | | | | |
| | | | | | 0x1 Always operate in Continuous Conduction Mode (CCM). | | | | |
| | | | | | | | | | |
| | 1:0 | | R/W | 0x0 | Reserved | | | | |
| BUCK1_D | | t | i | | | | | | |
| 0x72 | 7:0 | BUCK1_DVS0VOUT92[7:0] | R/W | TRIM | Upper eight bits of a 10-bit DAC[9:0] value to generate V _{OUT} for | | | | |
| | | | | | DVS Configuration 0. | | | | |
| | | | | | Note: V _{OUT} must be programmed above 0.3V. FBDIV is set by factory OTP to 1x, 0.8x, 0.6x. | | | | |
| | | | | | FBDIV 1.0 0.8 0.6 | | | | |
| | | | | | DAC V _{OUT} (V) V _{OUT} (V) V _{OUT} (V) | | | | |
| | | | | | 0x000 0.0000 0.0000 0.0000 | | | | |
| | | | | | 0x001 0.0012 0.0015 0.0020 | | | | |
| | | | | | | | | | |
| | | | | | 0x200 0.6144 0.768 1.024 | | | | |
| | | | | | 0x201 0.6156 0.7695 1.026 | | | | |
| | | | | | | | | | |
| | | | | | 0x3E8 1.2 1.5 2.0 | | | | |
| | | | | | | | | | |



| Address | Bit | Name | R/W | Default | Description |
|--|------|---|-----|---------|--|
| BUCK1_D | VS00 | CFG0 | | | |
| Configuration 0. Note: When DVS Configuration 0 | | Lower two bits of a 10-bit DAC[9:0] value to generate V _{OUT} for DVS Configuration 0. Note: When DVS Configuration 0 is selected (by pins or registers) any write to BUCK1_DVS0CFG0 causes a DVS ramping to occur. | | | |
| | 5 | RSVD | R/W | 0x0 | Reserved |
| | 4:0 | Reserved | R | 0x0 | Reserved |
| BUCK1_D | VS10 | CFG1 | | | |
| 0x74 | 7:0 | BUCK1_DVS1VOUT92 | R/W | TRIM | Buck1 DVS1 Configuration 1, See <u>"BUCK1_DVS0CFG1"</u> for description |
| BUCK1_D | VS10 | CFG0 | | | |
| 0x75 | 7:6 | BUCK1_DVS1VOUT10 | R/W | TRIM | Buck1 DVS1 Configuration 0, See <u>"BUCK1_DVS0CFG0"</u> for description |
| | 5 | BUCK1_DVS1DECAY | R/W | 0x0 | |
| | 4:0 | BUCK1_DVS1RSVD | R | 0x0 | |
| BUCK1_D | VS20 | CFG1 | | | |
| 0x76 | 7:0 | BUCK1_DVS2VOUT92 | R/W | TRIM | Buck1 DVS2 Configuration 1, See <u>"BUCK1_DVS0CFG1"</u> for description |
| BUCK1_D | VS20 | CFG0 | | | |
| 0x77 | 7:6 | BUCK1_DVS2VOUT10 | R/W | TRIM | Buck1 DVS2 Configuration 0, See "BUCK1_DVS0CFG0" for description |
| | 5 | BUCK1_DVS2DECAY | R/W | 0x0 | |
| | 4:0 | BUCK1_DVS2RSVD | R | 0x0 | |
| BUCK1_D | VS30 | CFG1 | | | |
| 0x78 | 7:0 | BUCK1_DVS3VOUT92 | R/W | TRIM | Buck1 DVS3 Configuration 1, See <u>"BUCK1_DVS0CFG1"</u> for description |
| BUCK1_D | VS30 | CFG0 | | | |
| 0x79 | 7:6 | BUCK1_DVS3VOUT10 | R/W | TRIM | Buck1 DVS3 Configuration 0. See <u>"BUCK1_DVS0CFG0"</u> for description |
| | 5 | BUCK1_DVS3DECAY | R/W | 0x0 | |
| | 4:0 | BUCK1_DVS3RSVD | R | 0x0 | |
| BUCK1_D | vss | EL | | | |
| 0x7D | 7:3 | Reserved | R | 0x00 | Reserved |
| | 2 | BUCK1_DVSCTRL | R/W | 0x0 | |
| | | | | | BUCK1 DVS Control |
| | | | | | 0x0 Use BUCK1_DVSSELECT[1:0] to select active DVS configuration. |
| | | | | | See Dynamic Voltage Scaling (DVS) for more detail on how to use. |
| | 1:0 | BUCK1_DVSSELECT | R/W | 0x0 | BUCK1 DVS Selection |
| | | | | | 0x0 Use DVS0 voltage setting |
| | | | | | 0x1 Use DVS1 voltage setting |
| | | | | | 0x2 Use DVS2 voltage setting |
| | | | | | 0x3 Use DVS3 voltage setting |
| | | | | | Note: When BUCK1_DVSCTRL[0] = 0x0 any write to the register BUCK1_DVSSEL causes a DVS ramping event to occur. |



| Address | Bit | Name | R/W | Default | | D | escription | | | | |
|---------|-----|--------------------|-----|---------|------------------------------|-----------------|--|-----------------------------|--|--|--|
| BUCK1_R | SPC | FG1 | | | | | | | | | |
| 0x7E | 7 | BUCK1_RSPCFG1RSVD1 | R | 0x0 | Reserved | | | | | | |
| | 6:4 | BUCK1_RSPUP | R/W | 0x7 | This slew rate is voltage. | used when the o | current voltage is l | ess than the target | | | |
| | | | | | FBDIV = BUCH Slow = BUCK1 | _RSPUP[1:0], R | [1:0] = (1.0, 0.8, 0 | 6) | | | |
| | | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | | RSP | FBDIV | Fast | Slow | | | |
| | | | | | 0x0 | 1.0 | 12 | 3 | | | |
| | | | | | 0x1 | 1.0 | 24 | 6 | | | |
| | | | | | 0x2 | 1.0 | 58 | 14 | | | |
| | | | | | 0x3 | 1.0 | 115 | 29 | | | |
| | | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | RSP | FBDIV | Fast | Slow | | | | |
| | | | | | 0x0 | 0.8 | 12 | 3 | | | |
| | | | | | 0x1 | 0.8 | 24 | 6 | | | |
| | | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | | RSP | FBDIV | Fast | Slow | | | |
| | | | | | 0x0 | 0.6 | 12 | 3 | | | |
| | | | | | 0x1 | 0.6 | 24 | 6 | | | |
| | 3 | Reserved | R | 0x0 | Reserved | | | | | | |
| | 2:0 | BUCK1_RSPDN | R/W | 0x3 | voltage. | | current voltage is g decode information | greater than the targ n. | | | |



| Bit | Name | R/W | Default | Description | | | | | | |
|------|---|--|---|---|--|---|---|--|--|--|
| SPC | FG0 | | | | | | | | | |
| 7 | Reserved | R | 0x0 | Reserved | Reserved | | | | | |
| 6:4 | BUCK1_RSPPUP | R/W | 0x7 | | | current voltage is | 0V and the target is | | | |
| | | | | RSP = BUCK1 FBDIV = BUCK1 Slow = BUCK1 | _RSPUP[1:0], R K1_VOUTFBDIV I_RSPUP[2] = 0 | [1:0] = (1.0, 0.8, 0 | .6) | | | |
| | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | RSP | FBDIV | Fast | Slow | | | |
| | | | | 0x0 | 1.0 | 6 | 1.2 | | | |
| | | | | 0x1 | 1.0 | 12 | 3 | | | |
| | | | | 0x2 | 1.0 | 29 | 7.2 | | | |
| | | | | 0x3 | 1.0 | 58 | 15 | | | |
| | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | RSP | FBDIV | Fast | Slow | | | |
| | | | | 0x0 | 0.8 | 12 | 3 | | | |
| | | | | 0x1 | 0.8 | 24 | 6 | | | |
| | | | | | | V _{OUT} Ramp | Speed mV/µs | | | |
| | | | | RSP | FBDIV | Fast | Slow | | | |
| | | | | 0x0 | 0.6 | 12 | 3 | | | |
| | | | | 0x1 | 0.6 | 24 | 6 | | | |
| 3 | | R | 0x0 | Reserved | | | | | | |
| | _ | | | | s used when the | current voltage is | greater than OV and th | | | |
| 2.0 | | | 0.00 | target voltage is 0V. See BUCK1_RSPPUP bits above for decode | | | | | | |
| N_DI | LY | | | | | | | | | |
| 7:6 | Reserved | R | 0x0 | Reserved | | | | | | |
| 5:0 | BUCK1_EN_DLY | R/W | 0x00 | Delay time from BUCK1_EN and IO_REGVAID go high to actual Buck1 V _{OUT} ramping up. | | | | | | |
| | | | | | - | , [] | | | | |
| | | | | 0x00 | 0 | | | | | |
| 1 | | | | 0x01 | 1ms | | | | | |
| | | | | 0.01 | | | | | | |
| | | | | 0x02 | 2ms | | | | | |
| | | | | - | 2ms | | | | | |
| | 7 6:4 3 2:0 7:6 | SPCFG0 7 Reserved 6:4 BUCK1_RSPPUP 8 BUCK1_RSPPUP 9 BUCK1_RSPPUP 10 BUCK1_RSPCFG0RSVD0 11 BUCK1_RSPPDN[2:0] 12 BUCK1_RSPPDN[2:0] | SPCF0 7 Reserved R 6:4 BUCK1_RSPPUP R/W 9 Superstandard State R 9 Superstandard State R 1 Superstandard State R | Image: SPCFG0 R 0x0 7 Reserved R 0x0 6:4 BUCK1_RSPPUP R/W 0x7 8 Suck1_RSPPUP R/W 0x7 9 Suck1_RSPCFGORSVD0 R 0x0 13 BUCK1_RSPPDN[2:0] R/W 0x3 13 BUCK1_RSPPDN[2:0] R/W 0x3 | SPCFG0 R 0x0 Reserved 6:4 BUCK1_RSPPUP R/W 0x7 This slew rate is greater than 0V Signature Vout Ramp Signature RSP = BUCK1 FBDIV = BUCK1 FBDIV = BUCK1 R RSP 0x0 0x1 0x2 0x3 RSP 0x0 0x1 0x2 0x3 0x1 0x2 0x3 RSP 0x0 0x1 0x2 0x3 0x1 0x2 0x3 RSP 0x0 0x1 0x2 0x3 RSP 0x0 0x1 0x2 0x0 0x1 0x2 0x3 RSP 0x0 0x1 0x1 0x0 0x1 0x2 0x3 RSP 0x0 0x1 0x1 0x0 0x1 0x2 0x3 1 RSP 0x0 0x1 1 RSP 0x0 0x1 1 RSP 0x0 0x1 1 RSP 0x0 Reserved 2:0 <td>SPCFG0 7 Reserved R 0x0 Reserved 6:4 BUCK1_RSPPUP R/W 0x7 This slew rate is used when the greater than 0V. Vout_Ramp Slew Rate RSP = BUCK1_RSPUP(1:0), R RSP = BUCK1_RSPUP(2) = 0 FBDIV = BUCK1_RSPUP(2) = 0 Slow = BUCK1_RSPUP(2) = 1 RSP = BUCK1_RSPUP(2) = 1 RSP = BUCK1_RSPUP(2) = 1 RSP FBDIV 0x0 1.0 0x1 1.0 0x2 1.0 0x3 1.0 0x3 1.0 0x4 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x4 0x0 0.8 0x1 0x0 0.8 0x1 0.8 0x1 0.8 0x1 0.8 0x0 0.8 0x1 0.8 0x1 0.8 0x1 0.8 0x0 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 <td< td=""><td>SPCFG0 7 Reserved R 0x0 Reserved 6.4 BUCK1_RSPPUP R/W 0x7 This slew rate is used when the current voltage is greater than 0V. Vour Ramp Slew Rate RSP = BUCK1_RSPUP[10]. Ramp Speed FBDIV = BUCK1_RSPUP[2] = 0 Vour Ramp FBDIV Vour Ramp Fast 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP RSP FBDIV 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP FBDIV RSP FBDIV Fast 0x0 0.8 12 0x1 0.8 24 Vour Ramp RSP FBDIV Fast 0x0 0.6 12 0x1 0.6 24 10 3 BUCK1_RSPCFG0RSVD0 R 0x0 Reserved 3 BUCK1_RSPPDN[2:0] R/W</td></td<></td> | SPCFG0 7 Reserved R 0x0 Reserved 6:4 BUCK1_RSPPUP R/W 0x7 This slew rate is used when the greater than 0V. Vout_Ramp Slew Rate RSP = BUCK1_RSPUP(1:0), R RSP = BUCK1_RSPUP(2) = 0 FBDIV = BUCK1_RSPUP(2) = 0 Slow = BUCK1_RSPUP(2) = 1 RSP = BUCK1_RSPUP(2) = 1 RSP = BUCK1_RSPUP(2) = 1 RSP FBDIV 0x0 1.0 0x1 1.0 0x2 1.0 0x3 1.0 0x3 1.0 0x4 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x3 1.0 0x4 0x0 0.8 0x1 0x0 0.8 0x1 0.8 0x1 0.8 0x1 0.8 0x0 0.8 0x1 0.8 0x1 0.8 0x1 0.8 0x0 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 0x1 0.6 <td< td=""><td>SPCFG0 7 Reserved R 0x0 Reserved 6.4 BUCK1_RSPPUP R/W 0x7 This slew rate is used when the current voltage is greater than 0V. Vour Ramp Slew Rate RSP = BUCK1_RSPUP[10]. Ramp Speed FBDIV = BUCK1_RSPUP[2] = 0 Vour Ramp FBDIV Vour Ramp Fast 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP RSP FBDIV 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP FBDIV RSP FBDIV Fast 0x0 0.8 12 0x1 0.8 24 Vour Ramp RSP FBDIV Fast 0x0 0.6 12 0x1 0.6 24 10 3 BUCK1_RSPCFG0RSVD0 R 0x0 Reserved 3 BUCK1_RSPPDN[2:0] R/W</td></td<> | SPCFG0 7 Reserved R 0x0 Reserved 6.4 BUCK1_RSPPUP R/W 0x7 This slew rate is used when the current voltage is greater than 0V. Vour Ramp Slew Rate RSP = BUCK1_RSPUP[10]. Ramp Speed FBDIV = BUCK1_RSPUP[2] = 0 Vour Ramp FBDIV Vour Ramp Fast 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP RSP FBDIV 0x0 1.0 6 0x1 1.0 12 0x2 1.0 29 0x3 1.0 58 Vour Ramp RSP FBDIV RSP FBDIV Fast 0x0 0.8 12 0x1 0.8 24 Vour Ramp RSP FBDIV Fast 0x0 0.6 12 0x1 0.6 24 10 3 BUCK1_RSPCFG0RSVD0 R 0x0 Reserved 3 BUCK1_RSPPDN[2:0] R/W | | | |



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| Address | Bit | Name | R/W | Default | Description |
|---------|------|-----------------------|-----|---------|---|
| BUCK1_S | ниті | DN_DLY | | | • |
| 0x81 | 7:6 | Reserved | R | 0x0 | Reserved |
| | 5:0 | BUCK1_SHUTDN_DLY | R/W | 0x00 | Delay time from BUCK1_EN and IO_REGVAID go low to actual Buck1 V _{OUT} ramping down. Delay = (integer value of register) ms [1ms/LSB] See <u>"BUCK1_EN_DLY"</u> for description |
| BUCK2_E | A2 | | | | |
| 0x82 | 7:6 | BUCK2_VOUTFBDIV | R/W | 0x0 | Buck2 FBDIV Configuration. See <u>BUCK1_EA2</u> for description |
| | 5:0 | Reserved | R | 0x1B | Reserved |
| BUCK2_D | СМ | | | | |
| 0x85 | 7:3 | Reserved | N/A | 0x0 | Reserved |
| | 2 | BUCK1_FCCM | R/W | 0x0 | |
| | | | | | Forced Continuous Conduction Mode |
| | | | | | 0x0 Discontinuous Conduction Mode (DCM) allowed when load reaches 0A. |
| | | | | | 0x1 Always operate in Continuous Conduction Mode (CCM). |
| | 1:0 | Reserved | R/W | 0x0 | Reserved |
| BUCK2_D | VSOC | CFG1 | | | |
| 0x8E | 7:0 | BUCK2_DVS0VOUT92 | R/W | TRIM | See BUCK1_DVS0CFG1 |
| BUCK2_D | VSOC | CFG0 | | | |
| 0x8F | 7:6 | BUCK2_DVS0VOUT10 | R/W | TRIM | See BUCK1_DVS0CFG0 |
| | 5 | BUCK2_DVS0DECAY | R/W | 0x0 | |
| | 4:0 | Reserved | R | 0x0 | |
| BUCK2_D | VS10 | CFG1 | | | |
| 0x90 | 7:0 | BUCK2_DVS1VOUT92 | R/W | TRIM | See BUCK1_DVS0CFG0 |
| BUCK2_D | VS10 | CFG0 | | | |
| 0x91 | 7:6 | BUCK2_DVS1VOUT10 | R/W | TRIM | See BUCK1_DVS0CFG0 |
| | 5 | BUCK2_DVS1DECAY | R/W | 0x0 | |
| | 4:0 | Reserved | R | 0x0 | |
| BUCK2_D | VS20 | CFG1 | | | |
| 0x92 | 7:0 | BUCK2_DVS2VOUT92[7:0] | R/W | TRIM | See BUCK1_DVS0CFG1 |
| BUCK2_D | VS20 | CFG0 | | | |
| 0x93 | 7:6 | BUCK2_DVS2VOUT10 | R/W | TRIM | See BUCK1_DVS0CFG0 |
| | 5 | BUCK2_DVS2DECAY | R/W | 0x0 | |
| | 4:0 | Reserved | R | 0x0 | |
| BUCK2_D | VS30 | CFG1 | | | |
| 0x94 | 7:0 | BUCK2_DVS3VOUT92 | R/W | TRIM | See BUCK1_DVS0CFG1 |
| BUCK2_D | VS30 | CFG0 | | | |
| 0x95 | 7:6 | BUCK2_DVS3VOUT10 | R/W | TRIM | See BUCK1_DVS0CFG0 |
| | 5 | BUCK2_DVS3DECAY | R/W | 0x0 |] |
| | 4:0 | Reserved | R | 0x0 |] |



ISL91302BIK

10. Register Description by Address

| Address | Bit | Name | R/W | Default | Description |
|---------|------|-----------------------|-----|---------|--|
| BUCK2_V | OUT | MAXMSB | | | |
| 0x96 | 7:2 | Reserved | R | 0x00 | Reserved |
| | 1:0 | BUCK2_VOUTMAX98[1:0] | R/W | 0x3 | |
| | | | | | Upper two bits of V _{OUT} Maximum Programming Limit |
| | | | | | Data format is same as BUCK2_DVS[3:0]VOUT[9:0] |
| BUCK2_V | Ουτ | MAXLSB | 1 | | |
| 0x97 | 7:0 | BUCK2_VOUTMAXLSB[7:0] | R/W | 0xFF | |
| | | | | | Lower byte of V _{OUT} Maximum Programming Limit |
| | | | | | Data format is same as BUCK2_DVS[3:0]VOUT[9:0] |
| BUCK2_D | VSSI | EL | 1 | | |
| 0x99 | 7:3 | Reserved | R | 0x00 | See BUCK1_DVSSEL |
| | 2 | BUCK2_DVSCTRL | R/W | 0x0 | |
| | 1:0 | BUCK2_DVSSELECT | R/W | 0x0 | |
| BUCK2_F | SPC | FG1 | 1 | | |
| 0x9A | 7 | Reserved | R | 0x0 | See BUCK1_RSPCFG1 |
| | 6:4 | BUCK2_RSPUP | R/W | 0x7 | |
| | 3 | Reserved | R | 0x0 | |
| | 2:0 | BUCK2_RSPDN[2:0] | R/W | 0x3 | |
| BUCK2_R | SPC | FG0 | | | |
| 0x9B | 7 | Reserved | R | 0x0 | See BUCK1_RSPCFG0 |
| | 6:4 | BUCK2_RSPPUP[2:0] | R/W | 0x7 | |
| | 3 | Reserved | R | 0x0 | |
| | 2:0 | BUCK2_RSPPDN[2:0] | R/W | 0x3 | |
| BUCK2_E | N_DI | Y | | | |
| 0x9C | 7:6 | Reserved | R | 0x0 | See BUCK1 EN DLY |
| | 5:0 | BUCK2_EN_DLY | R/W | 0x00 | |
| BUCK2_S | ниті | DN_DLY | | | |
| 0x9D | 7:6 | Reserved | R | 0x0 | See BUCK1_SHUTDN_DLY |
| | 5:0 | BUCK2_SHUTDN_DLY | R/W | 0x00 | |



11. Revision History

| Rev. | Date | Description |
|------|-----------|---|
| 1.01 | Feb.25.20 | Removed addendum. |
| 1.00 | Dec.6.19 | Rewrite throughout. Addendum added on page 61. |
| 0.00 | Jul.26.18 | Initial release |



12. Package Outline Drawing

V35.4.7x6.3

35 Thin Profile Ball Grid Array Package (TFBGA) Rev 3, 10/19

For the most recent package outline drawing, see V35.4.7x6.3.



Bottom View



Typical Recommended Land Pattern

Notes:

- 1. All dimensions and tolerances conform to ASME Y14.5 2009.
- <u>(2)</u> Dimension is measured at the maximum solder ball diameter, parallel to primary datum <u>C</u>.
- A Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
- 4. Unless otherwise specified, dimensions are in millimeters.





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